

FIG. 1A

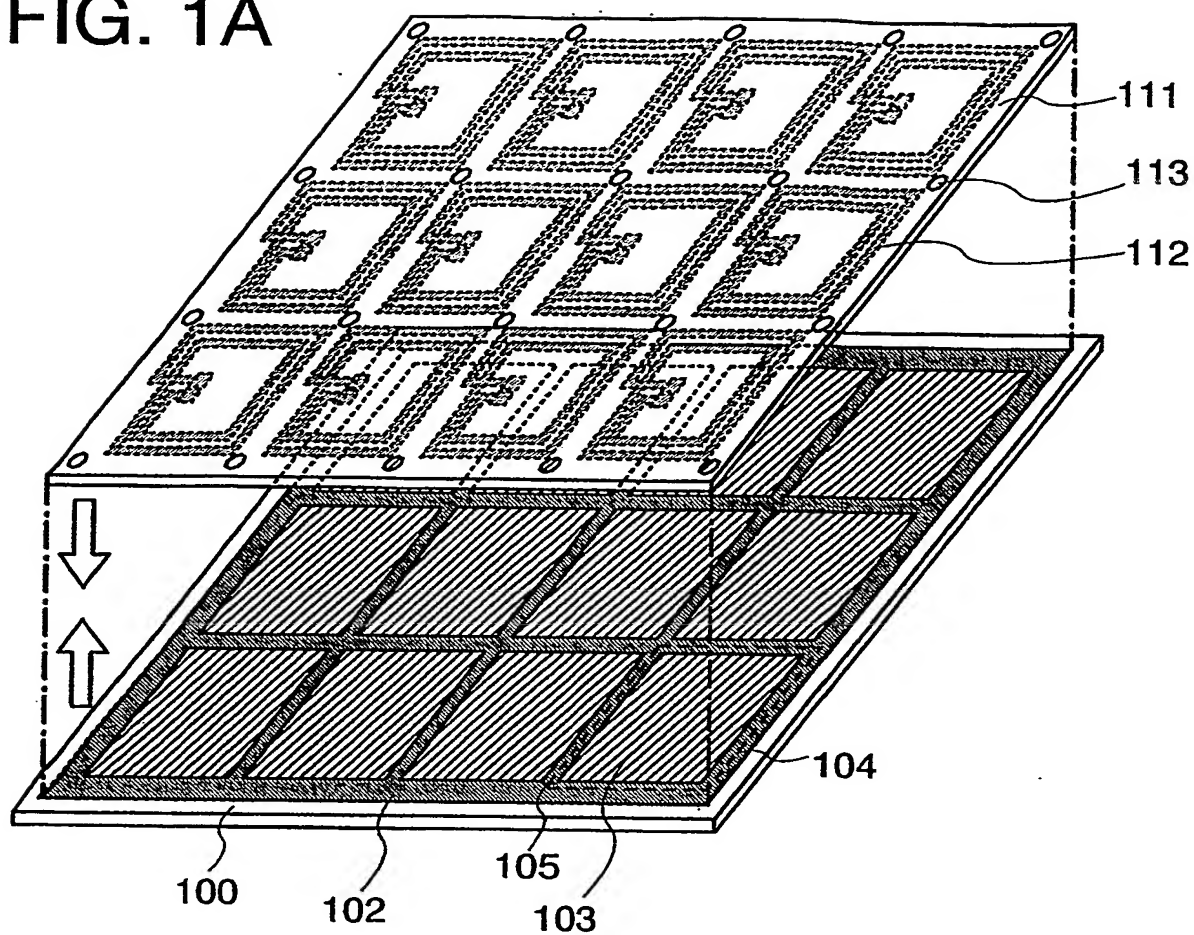
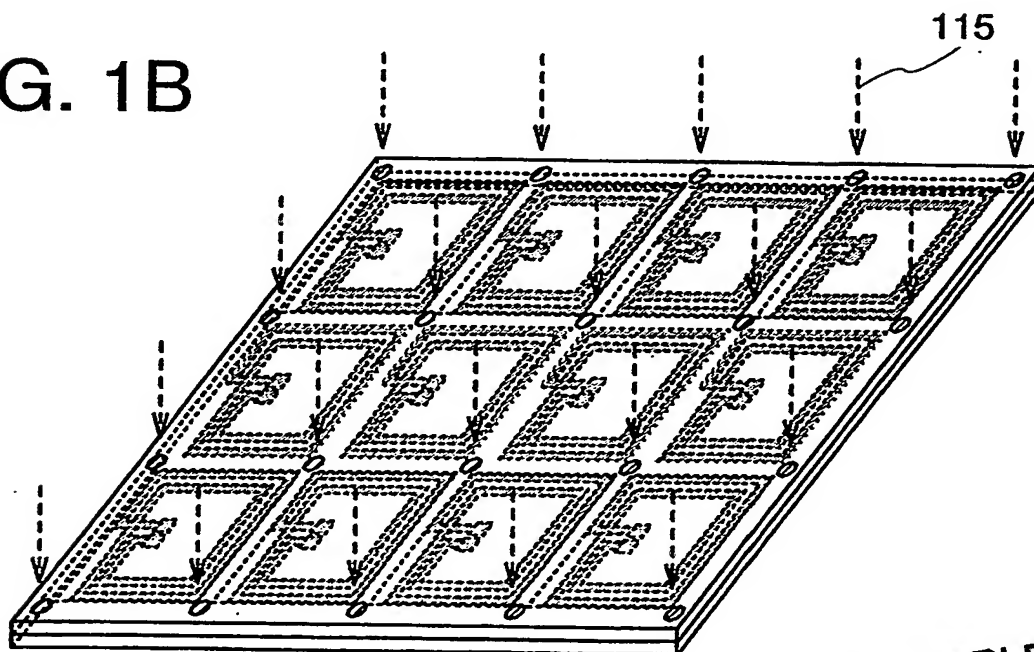


FIG. 1B



BEST AVAILABLE COPY

FIG. 2A

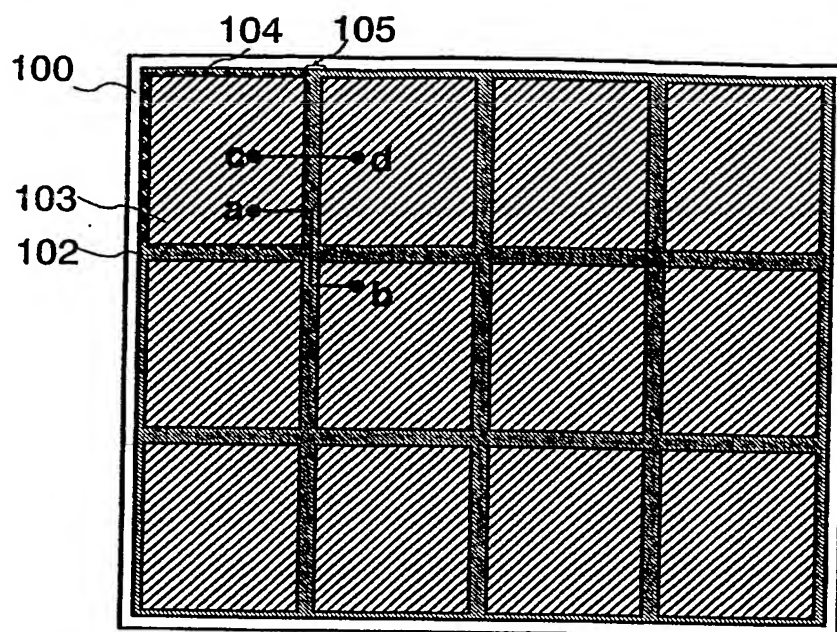


FIG. 2B

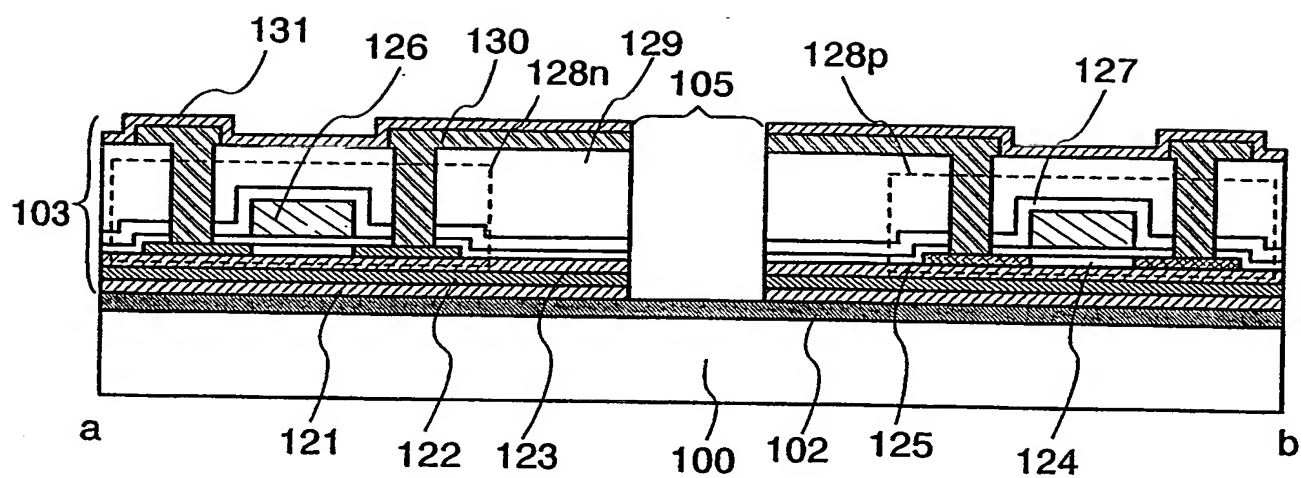


FIG. 2C

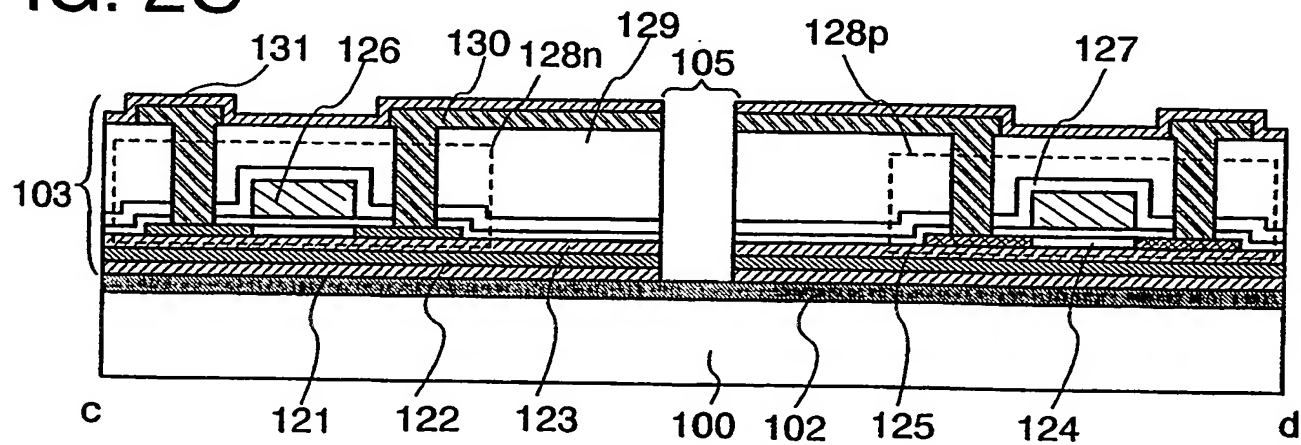


FIG. 3A

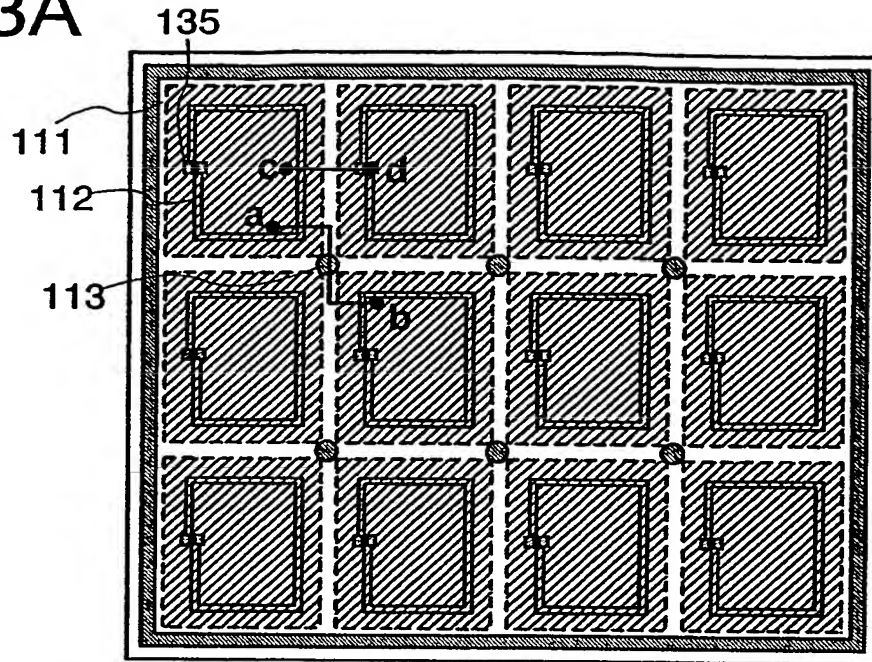


FIG. 3B

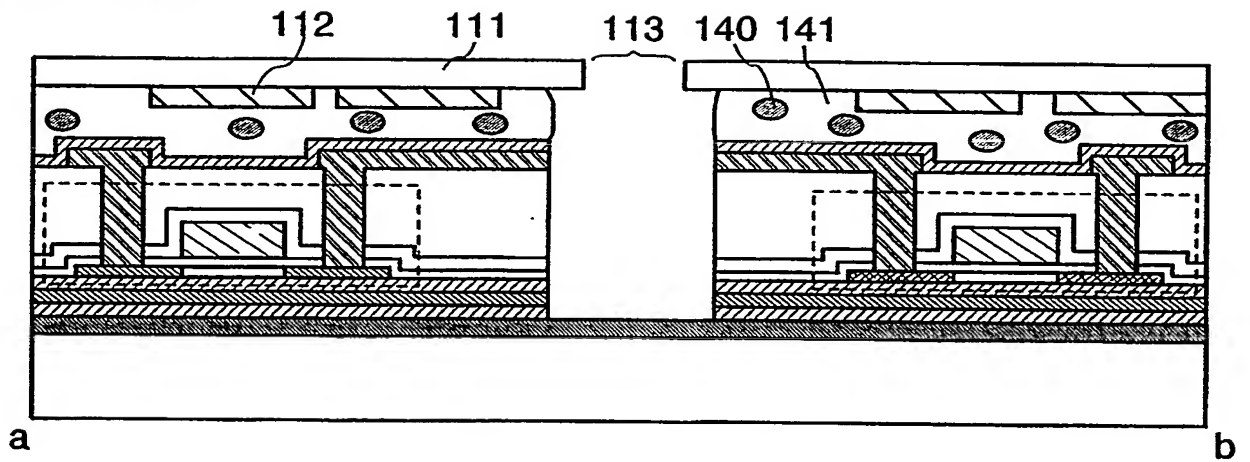


FIG. 3C

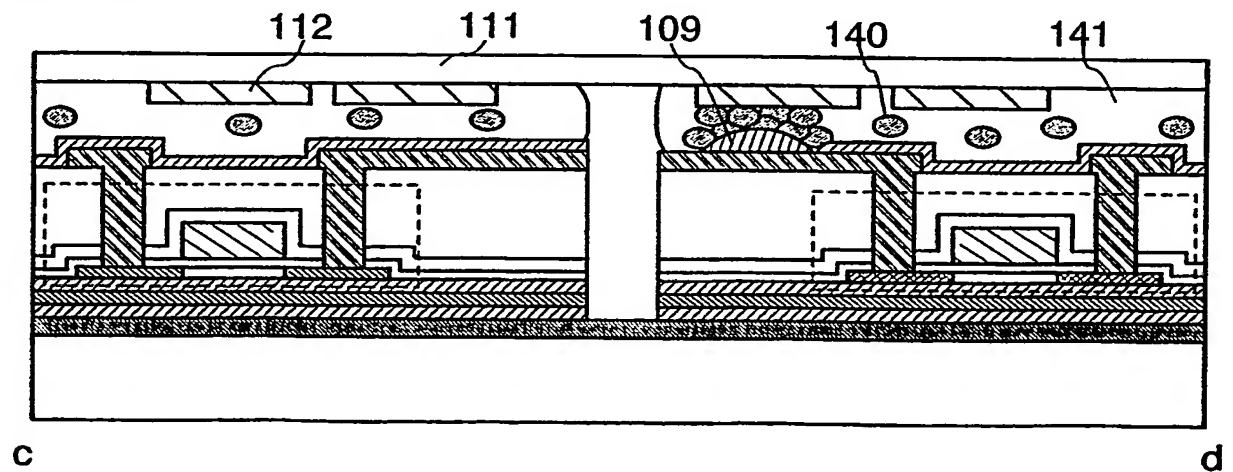


FIG. 4A

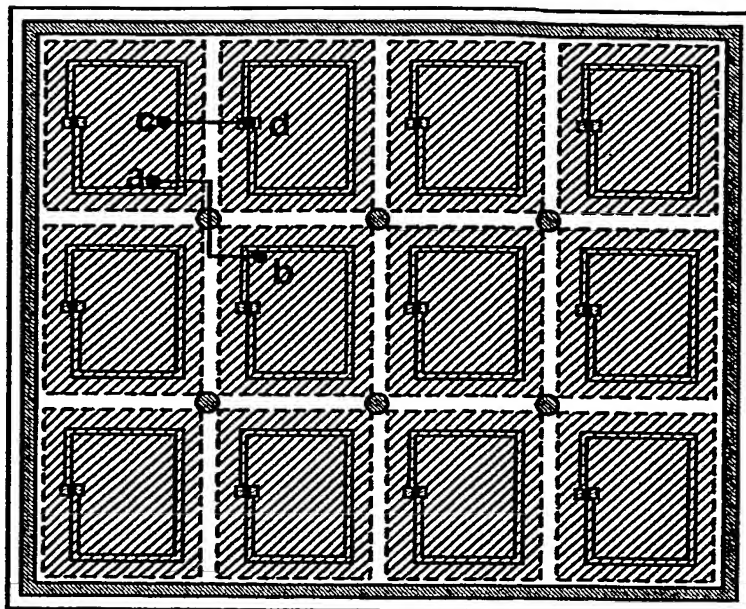


FIG. 4B

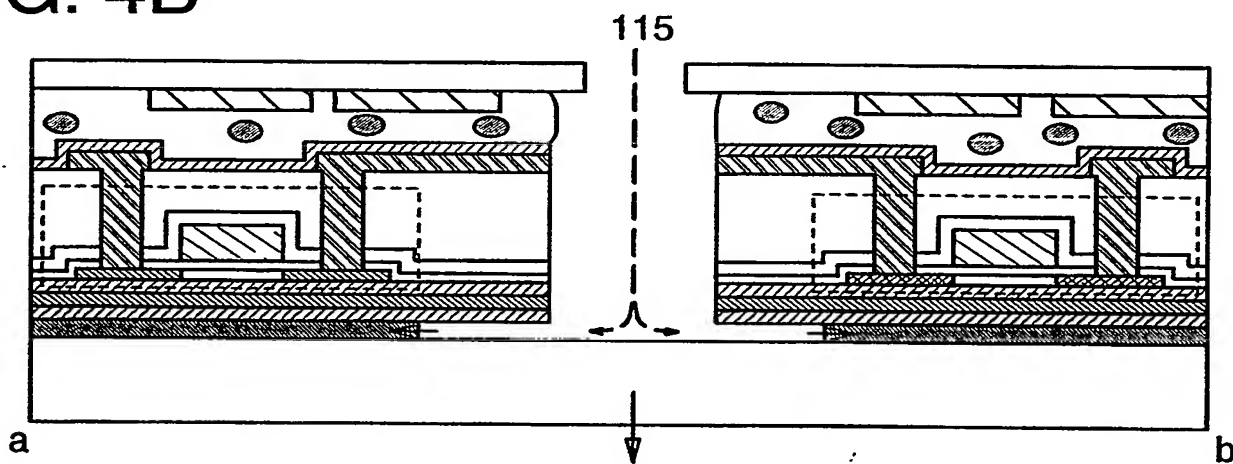


FIG. 4C

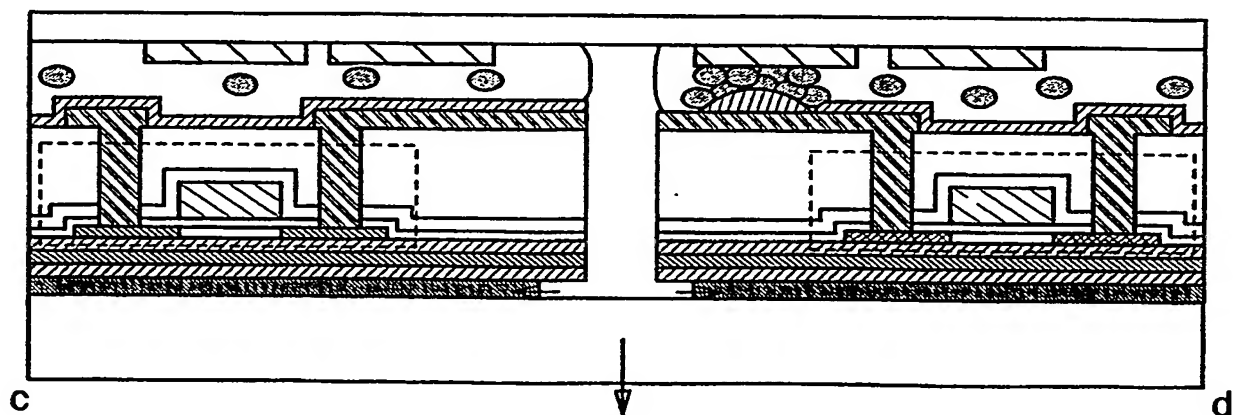


FIG. 5A

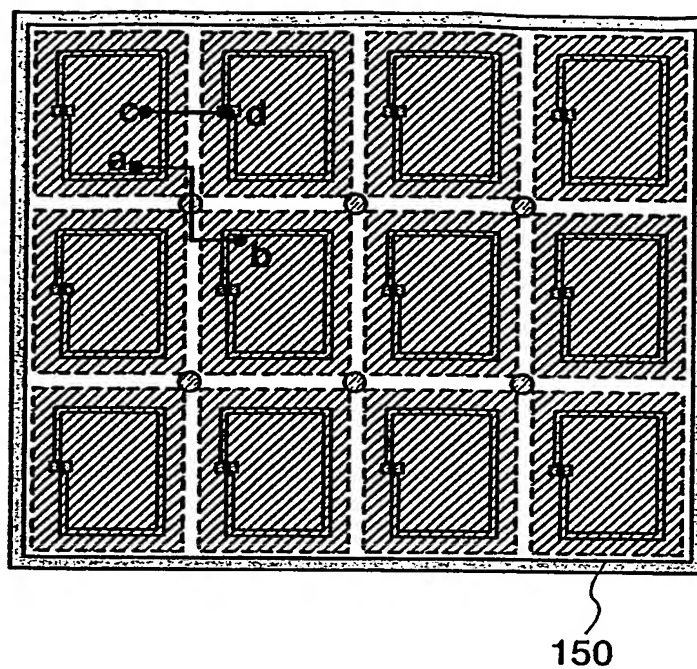


FIG. 5B

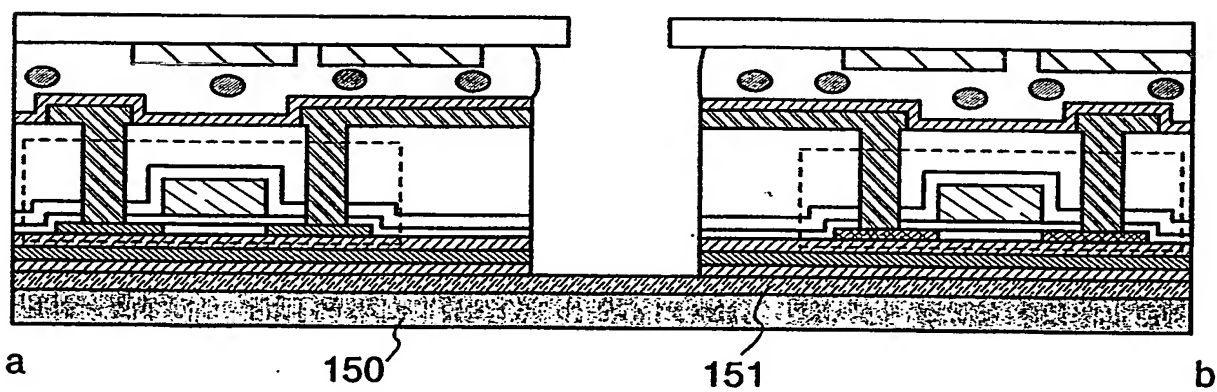


FIG. 5C

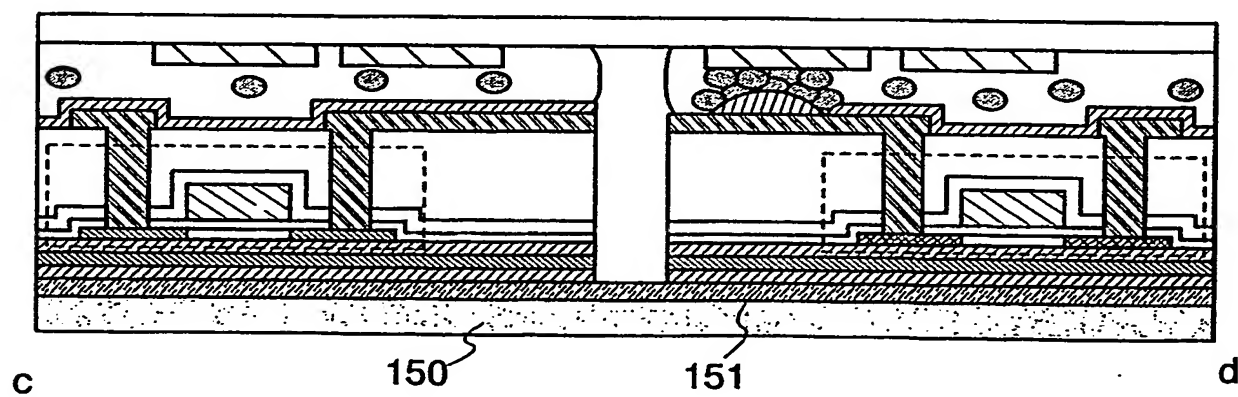


FIG. 6A

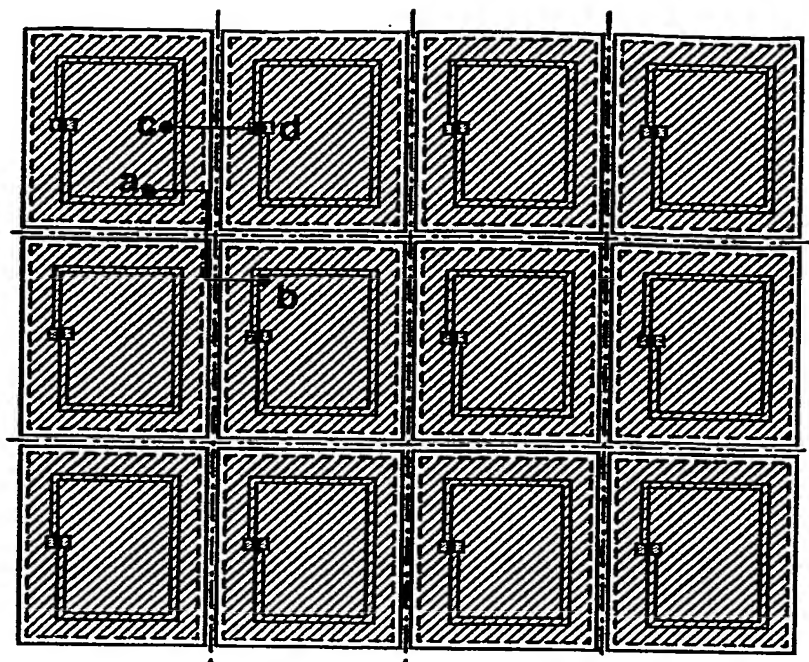
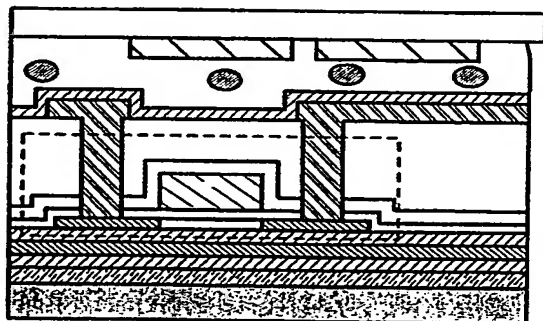
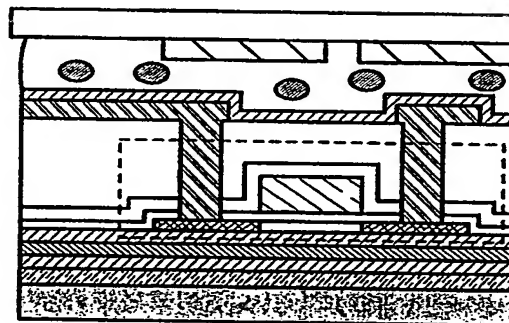


FIG. 6B

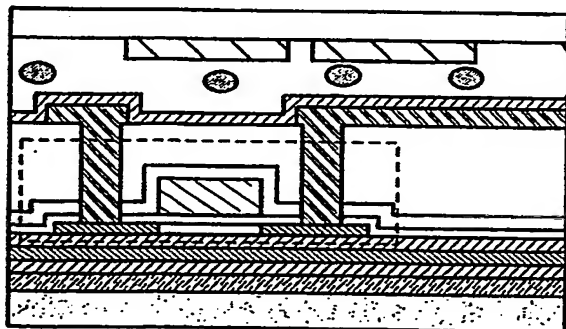


a

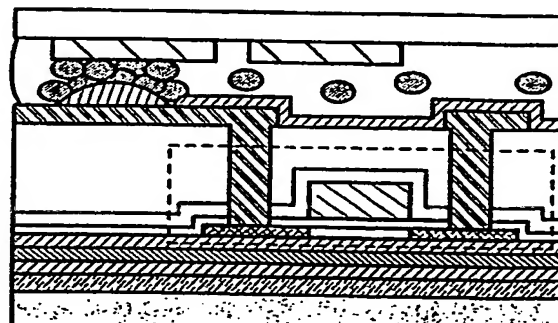


b

FIG. 6C



c



d

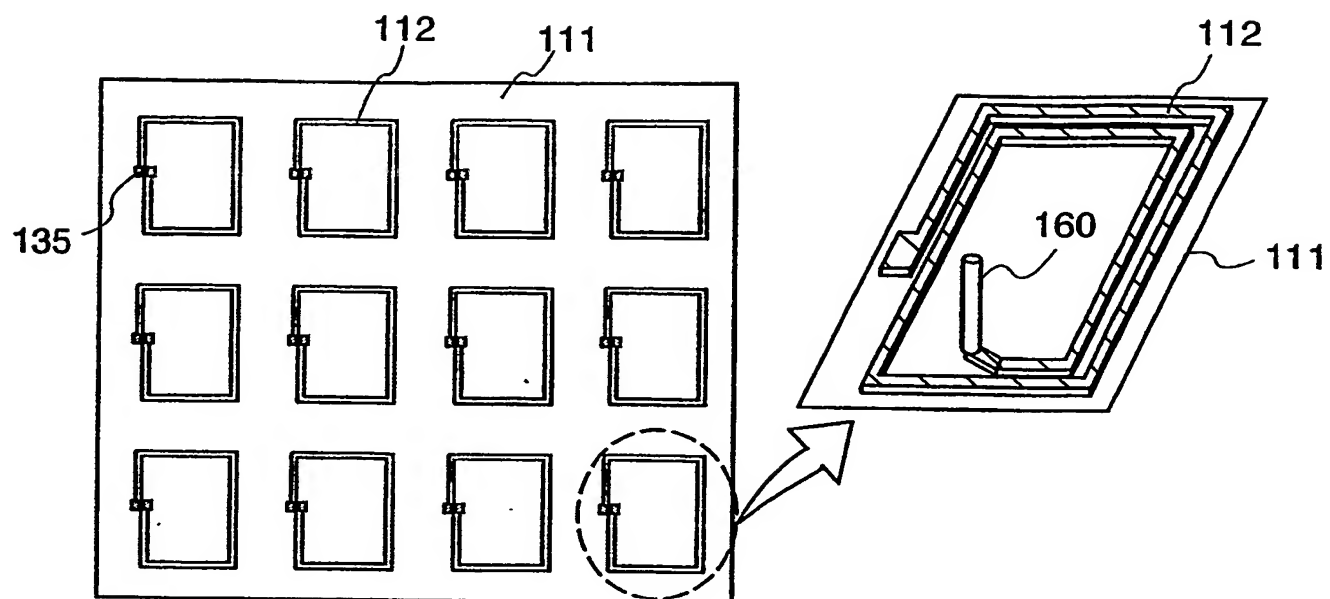


FIG. 7A

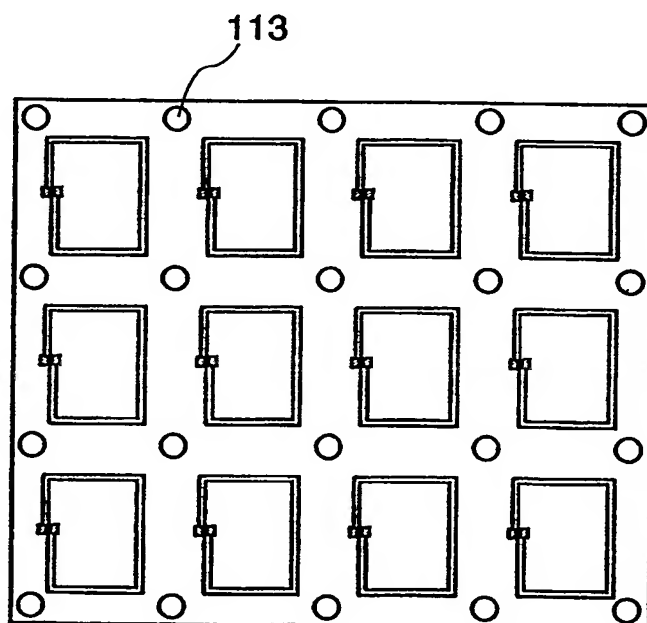


FIG. 7B



FIG. 8A

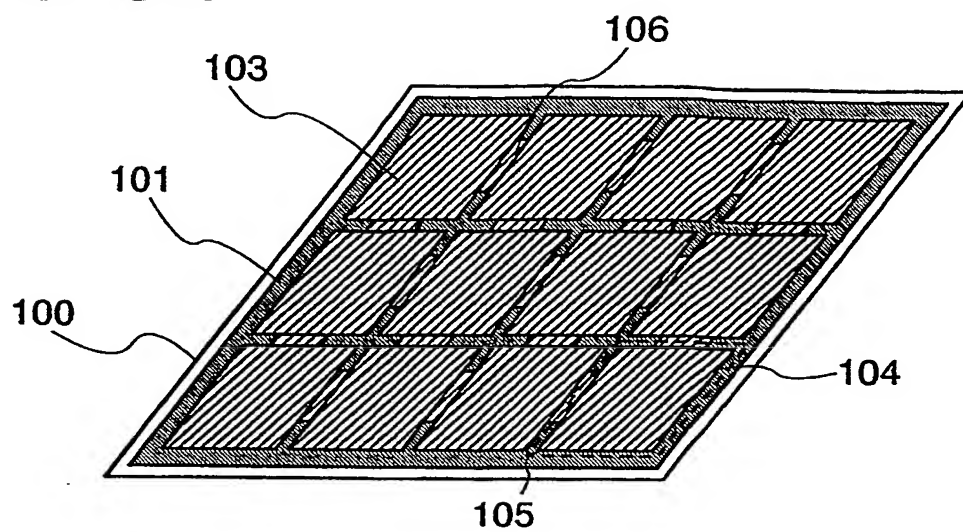


FIG. 8B

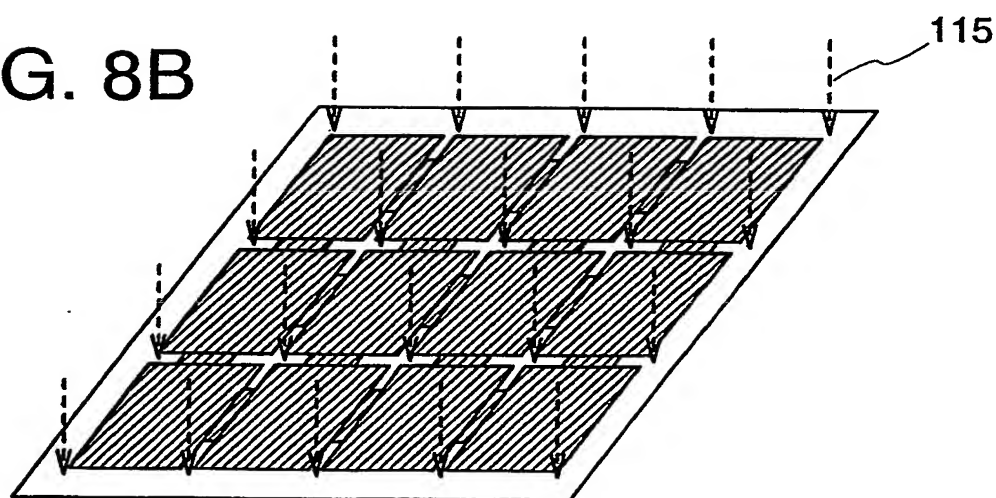


FIG. 8C

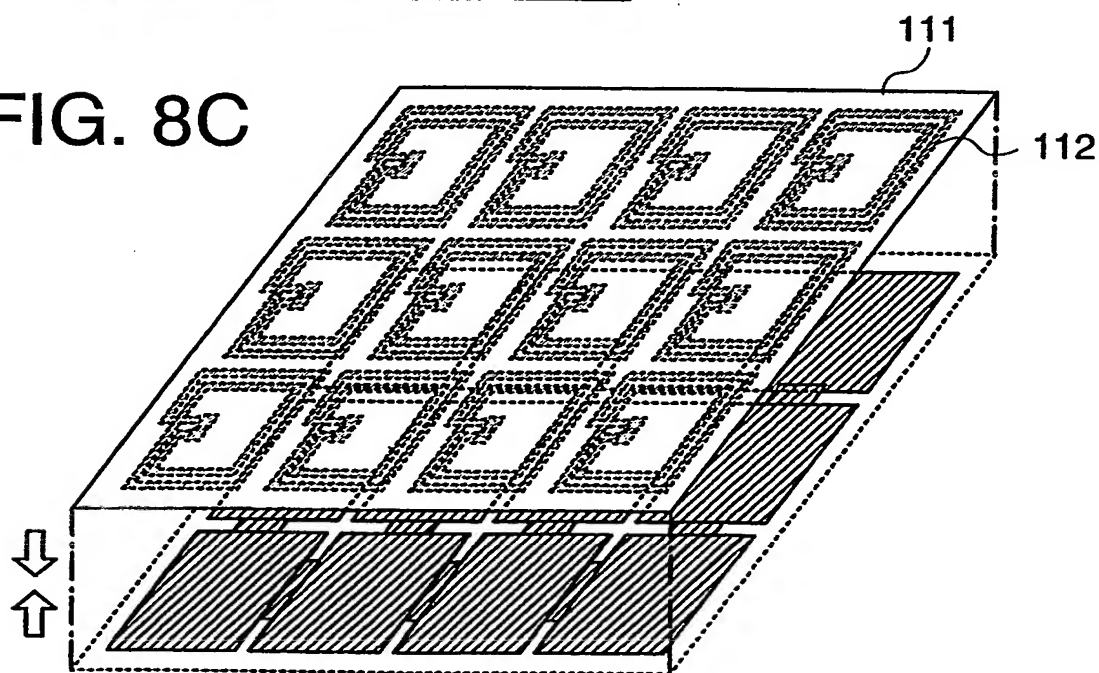




FIG. 9A

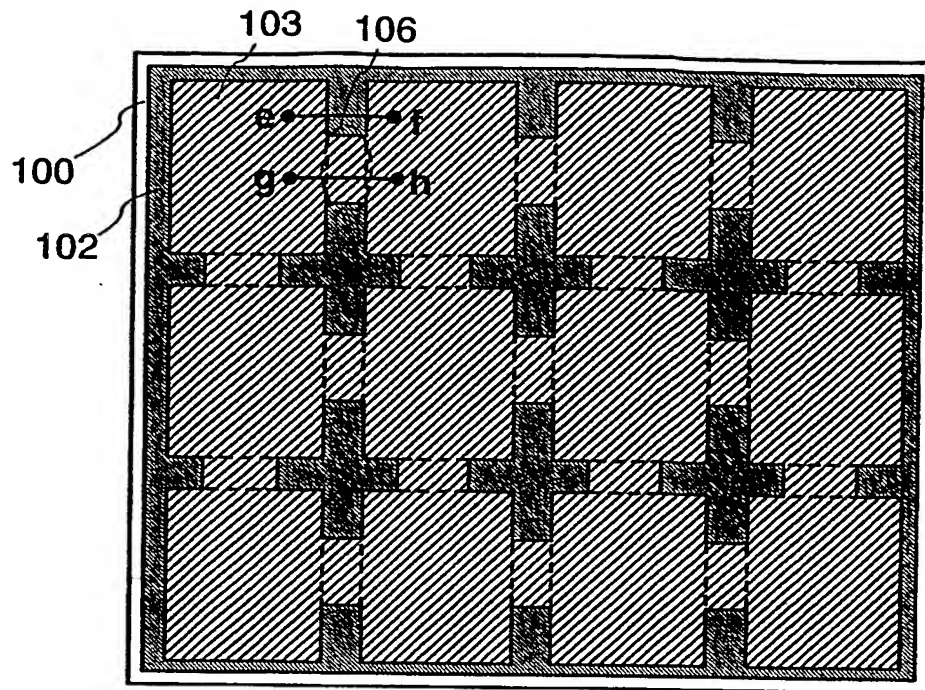


FIG. 9B

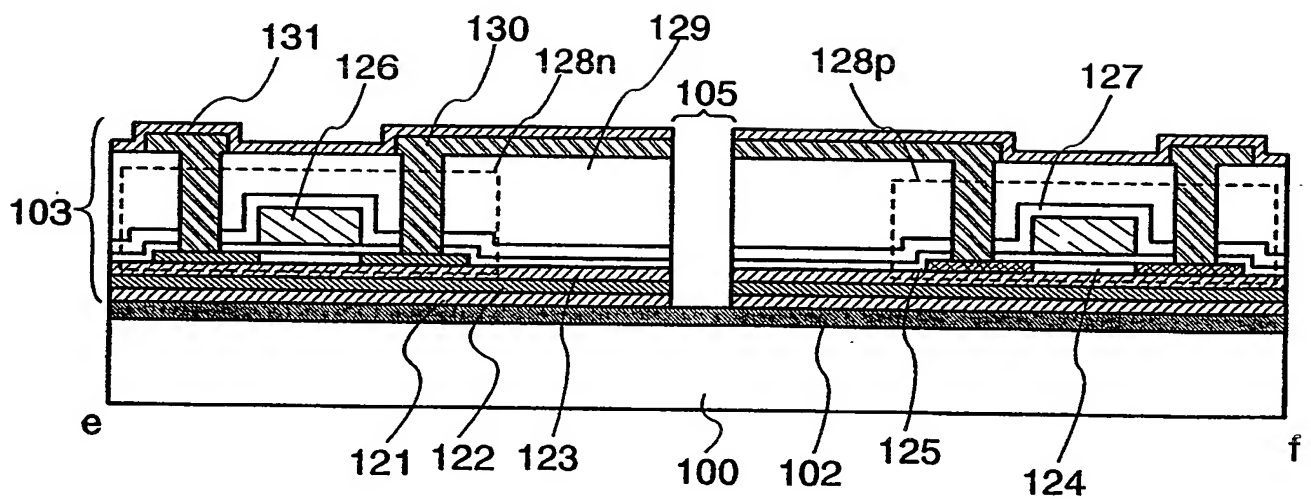


FIG. 9C

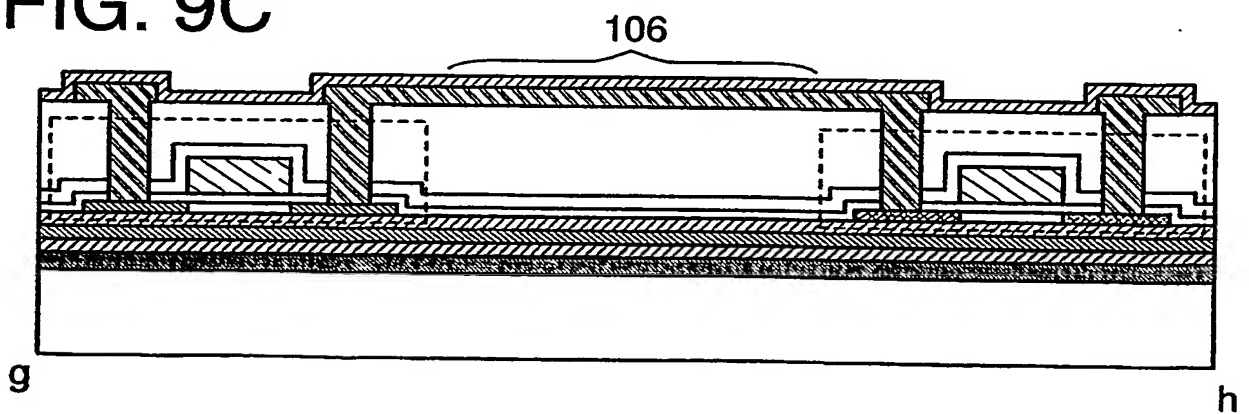


FIG. 10A

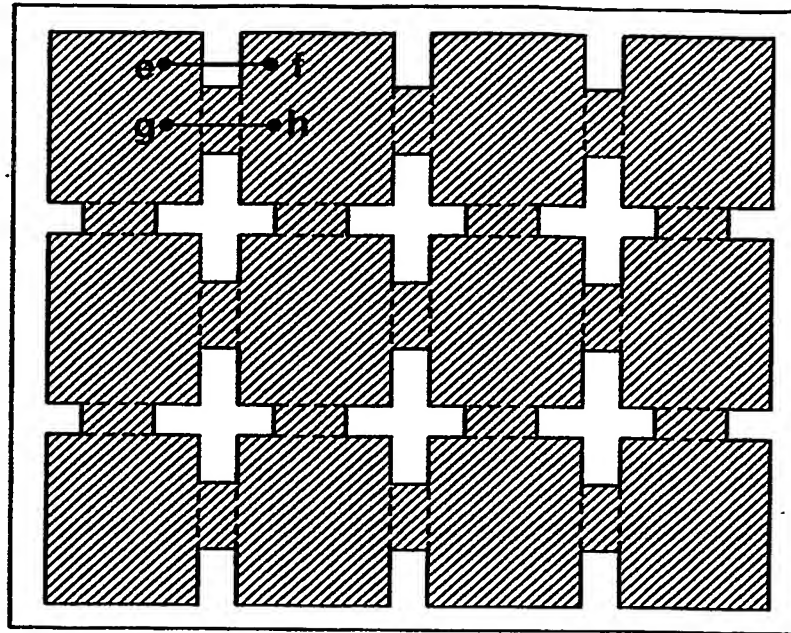


FIG. 10B

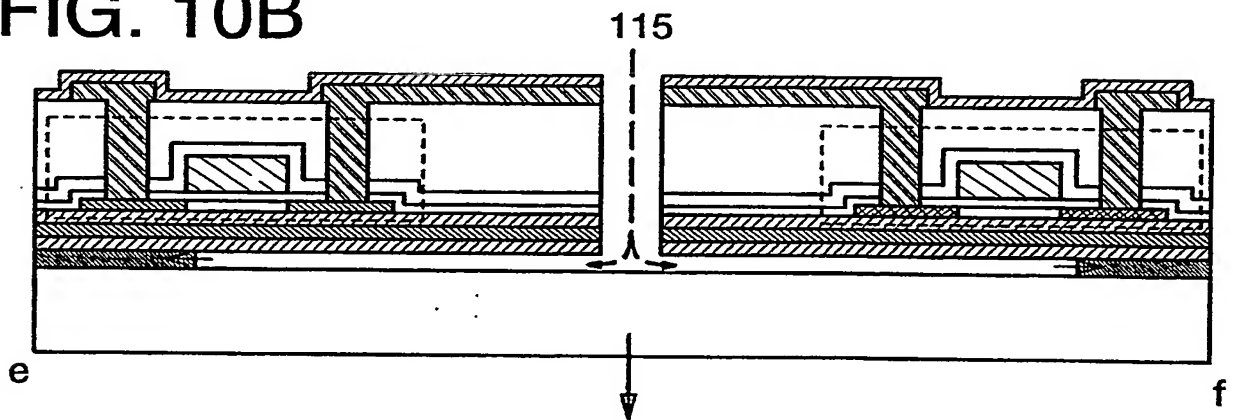


FIG. 10C

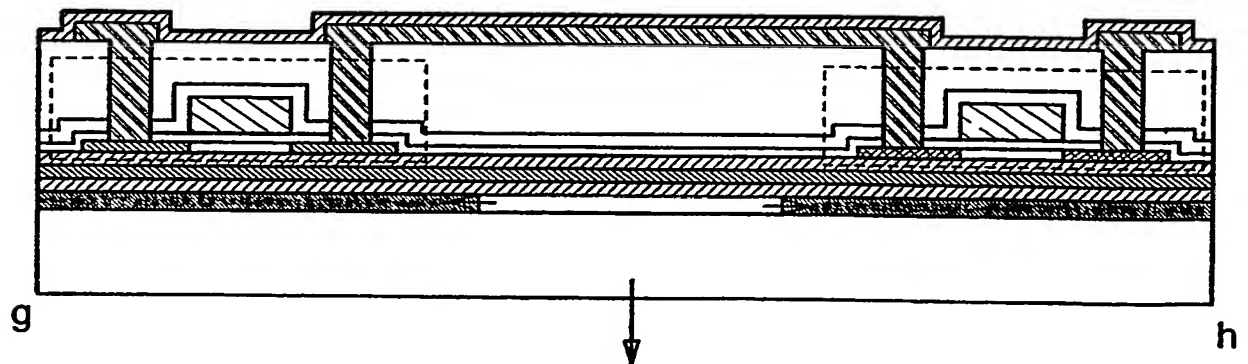


FIG. 11A

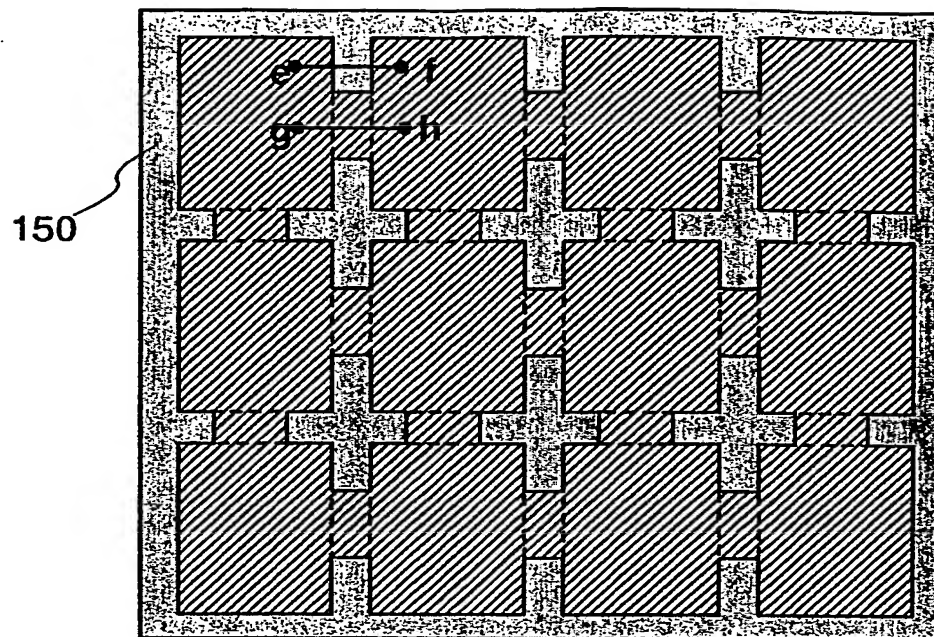


FIG. 11B

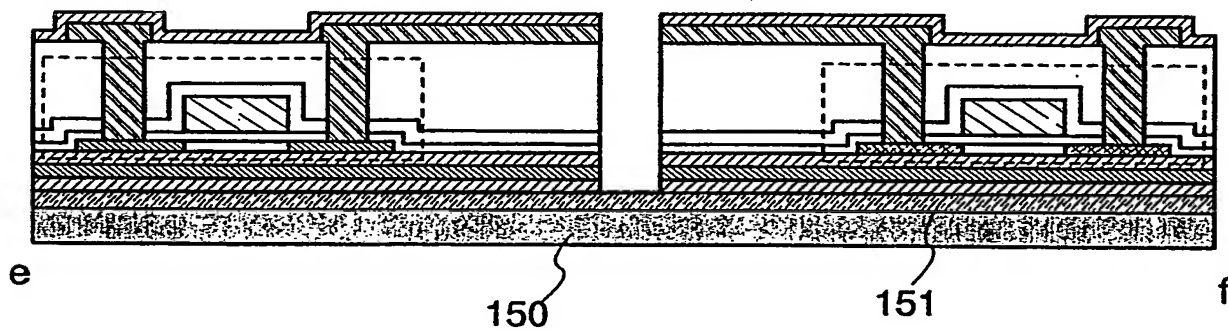


FIG. 11C

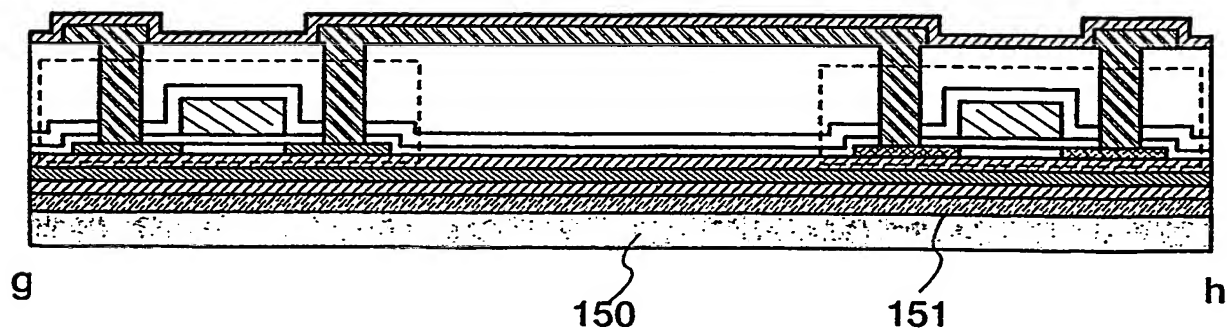


FIG. 12A

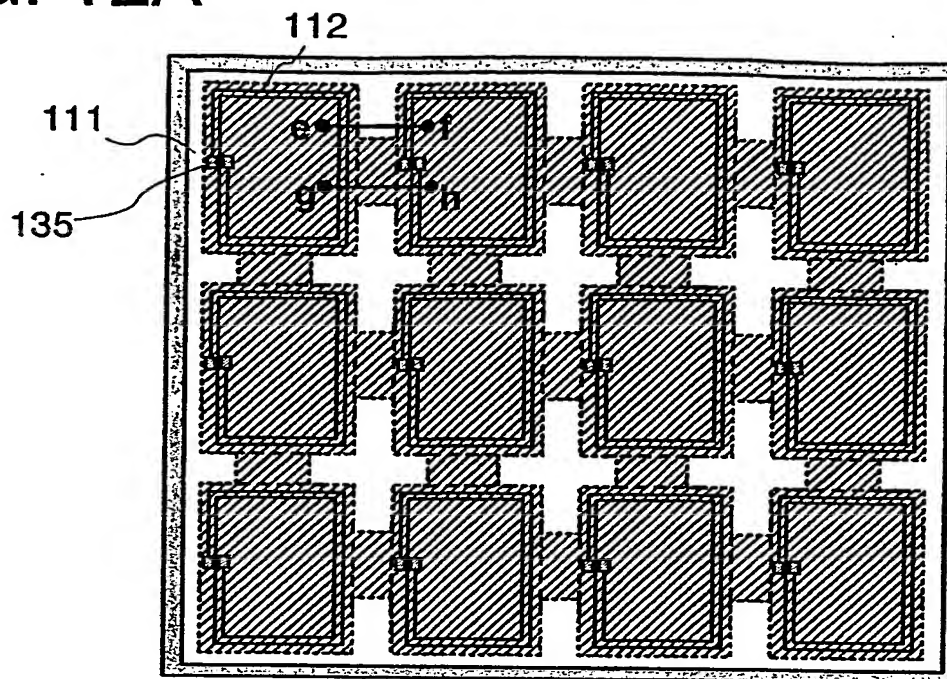


FIG. 12B

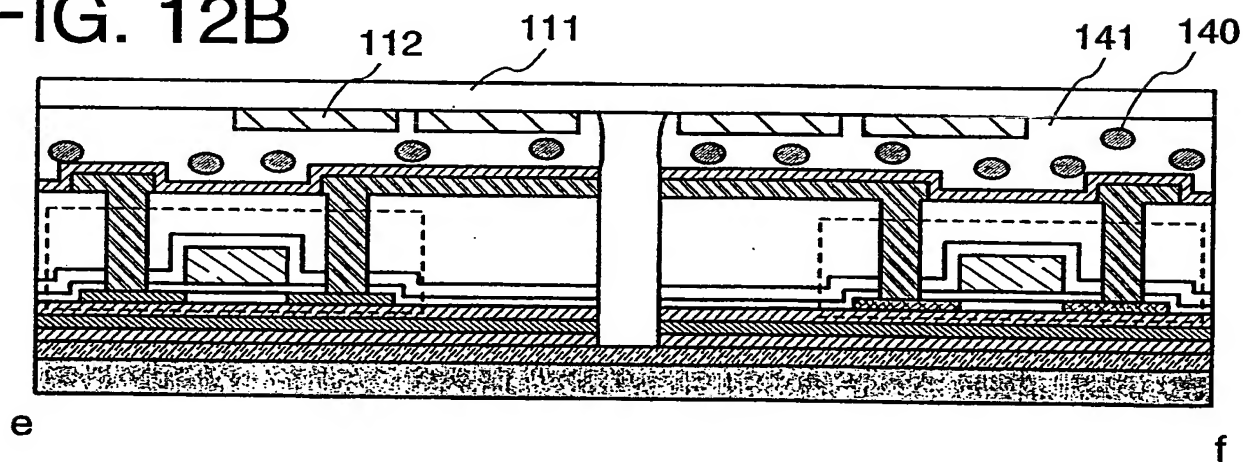


FIG. 12C

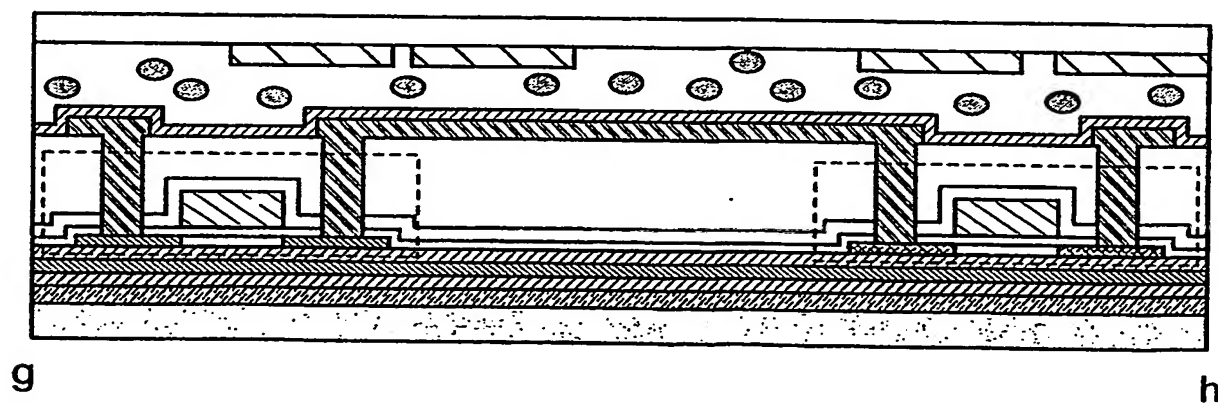


FIG. 13A

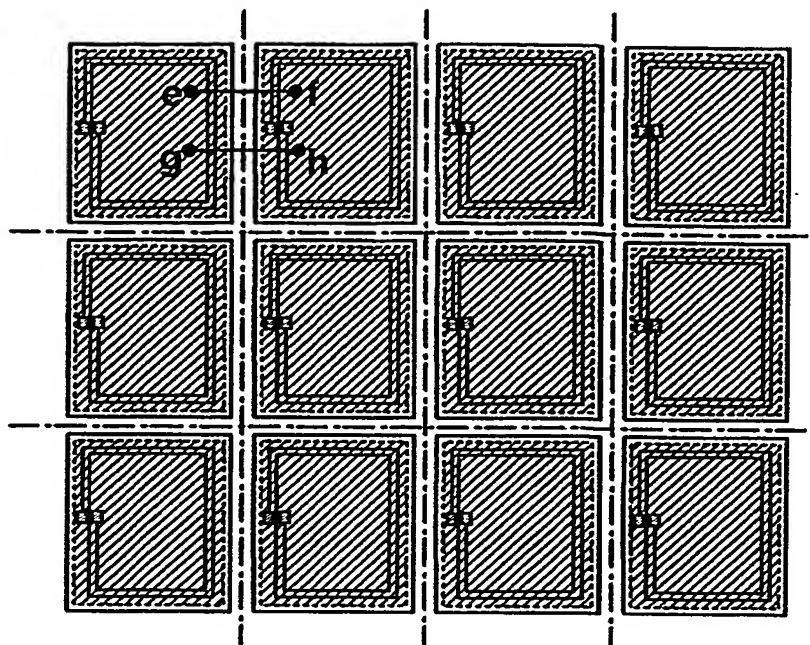
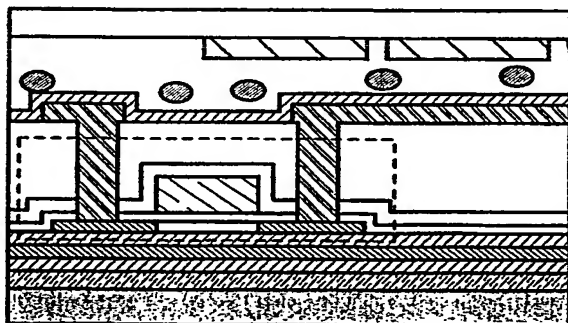
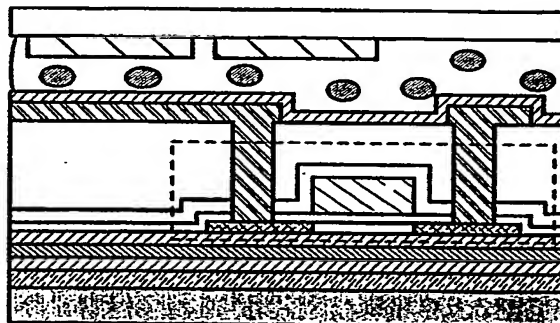


FIG. 13B

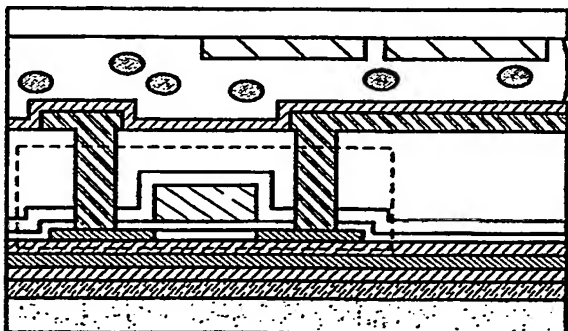


e

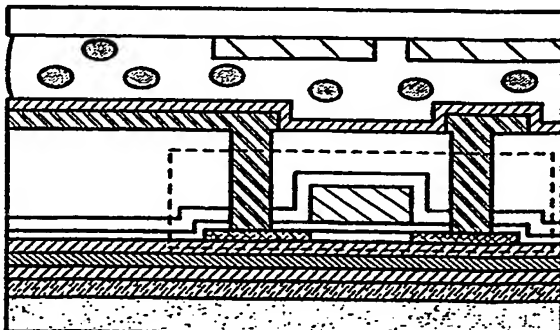


f

FIG. 13C



g



h

FIG. 14A

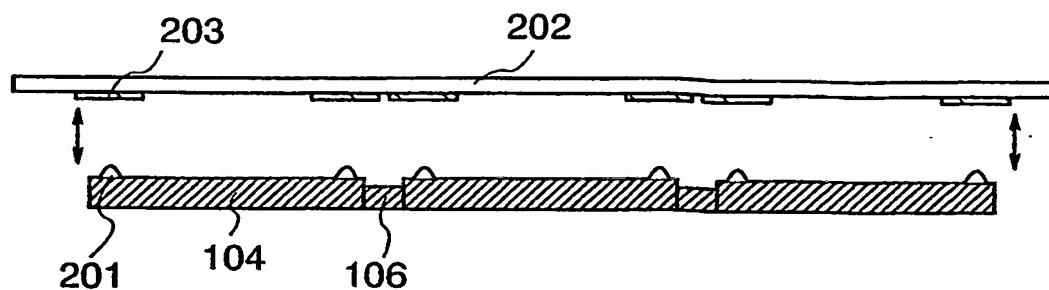


FIG. 14B



FIG. 14C

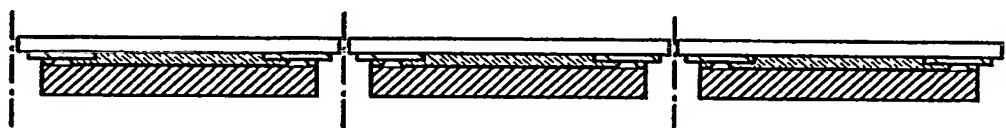
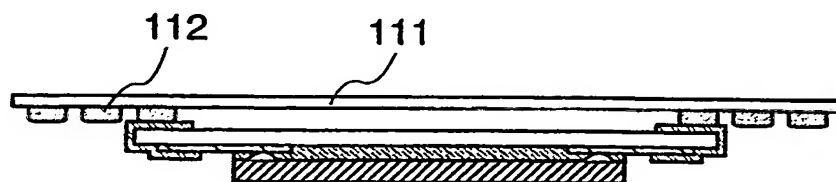


FIG. 14D



FIG. 14E





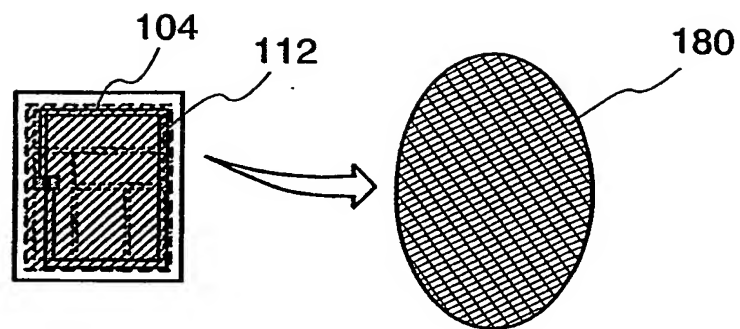


FIG. 15A

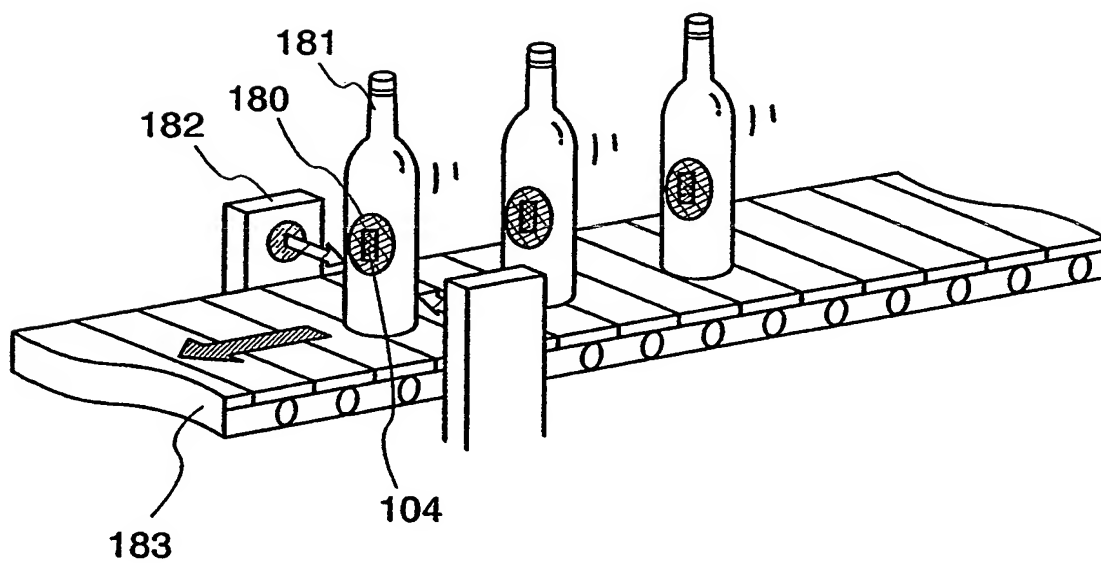


FIG. 15B

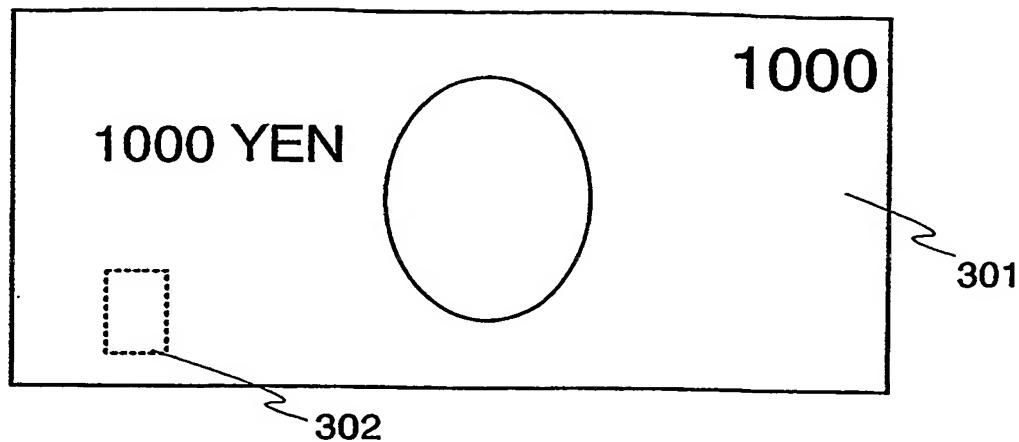


FIG. 16A

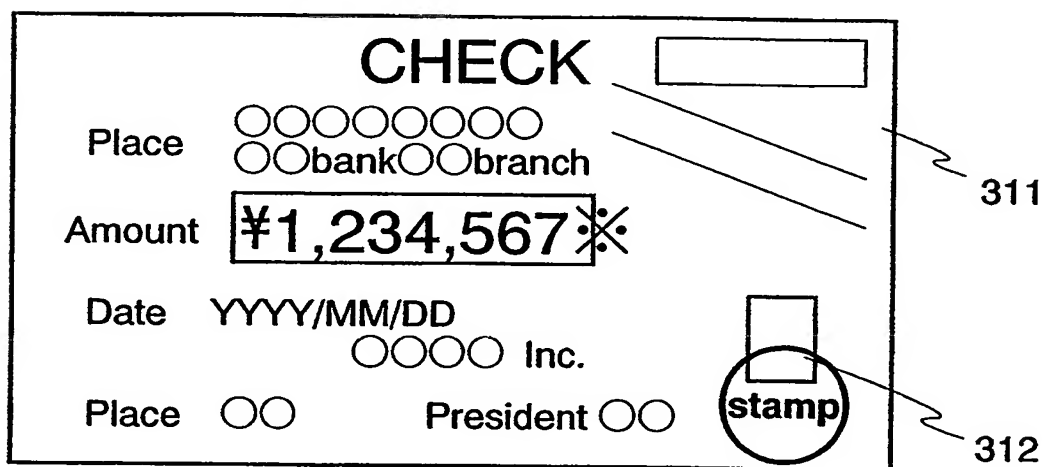


FIG. 16B

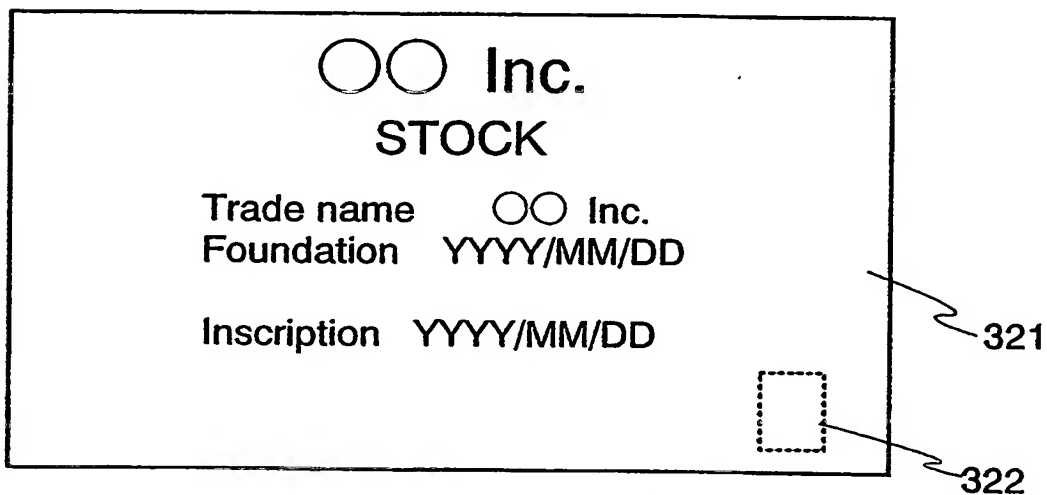


FIG. 16C

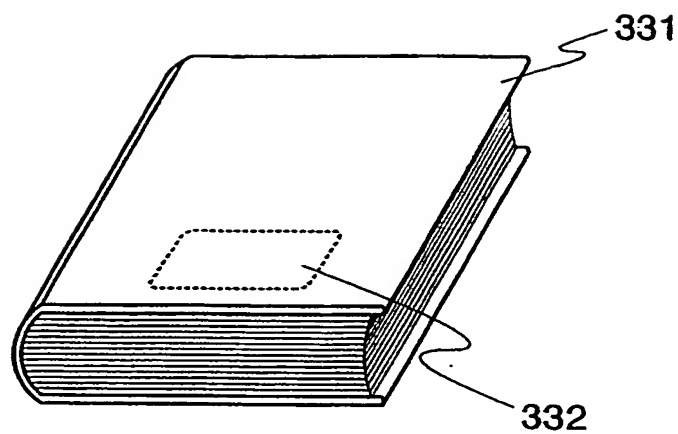


FIG. 17A

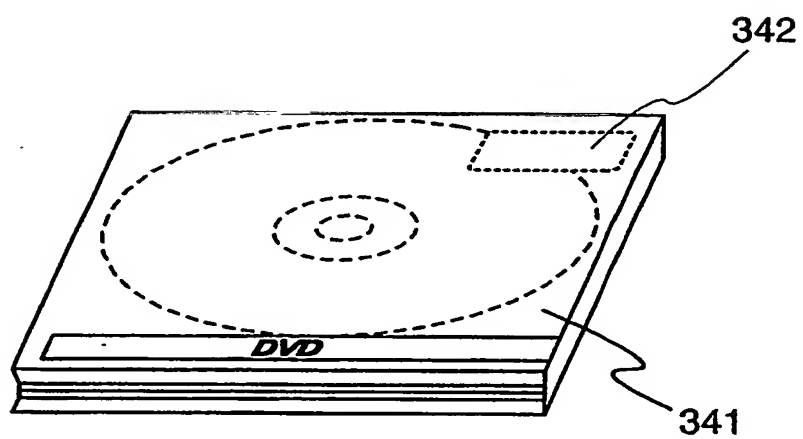


FIG. 17B

FIG. 18A

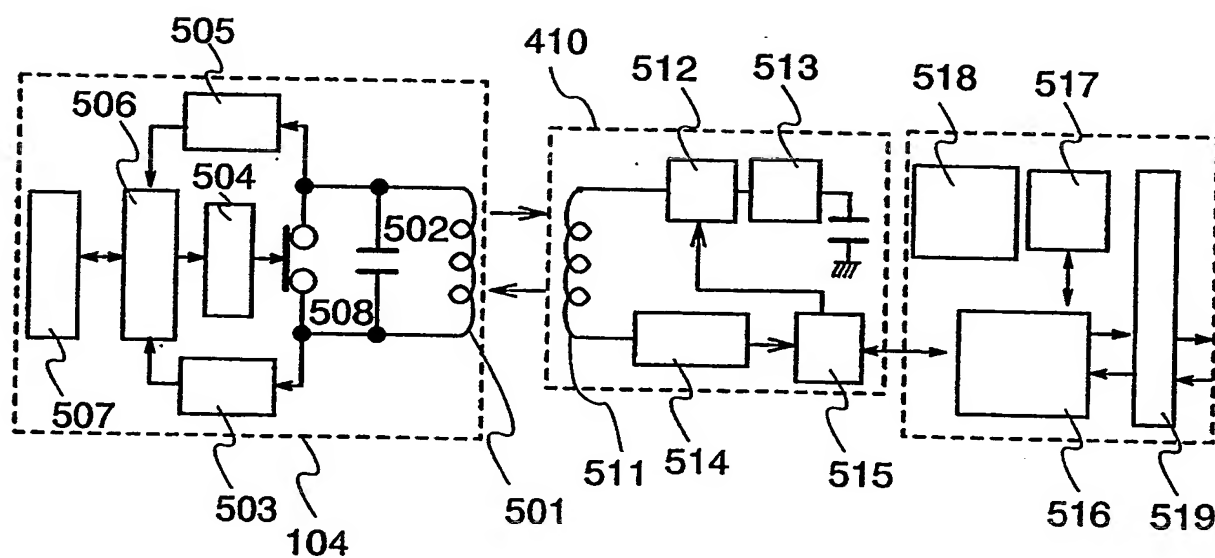
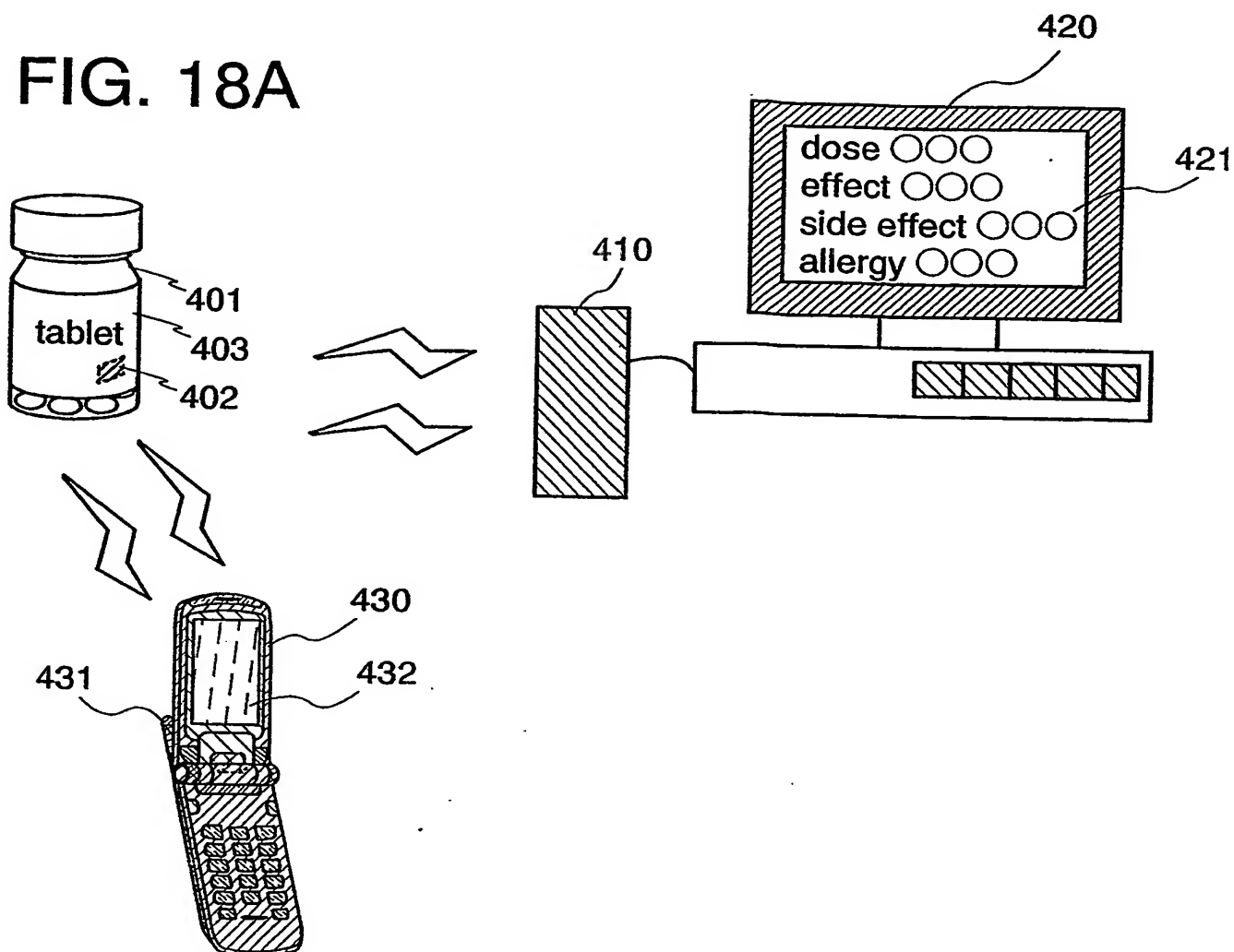


FIG. 18B

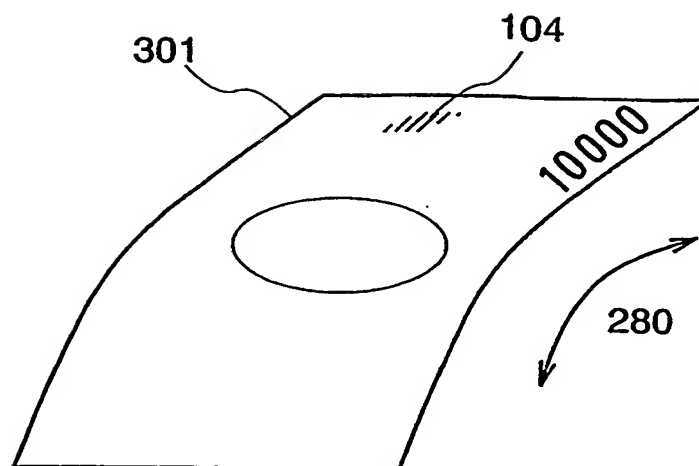


FIG. 19A

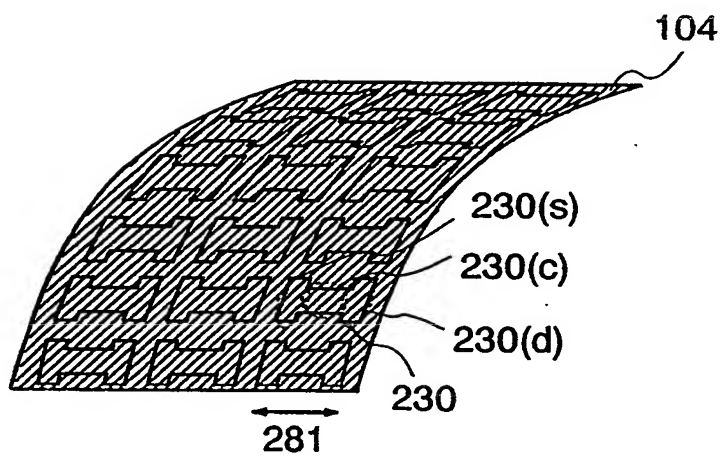


FIG. 19B

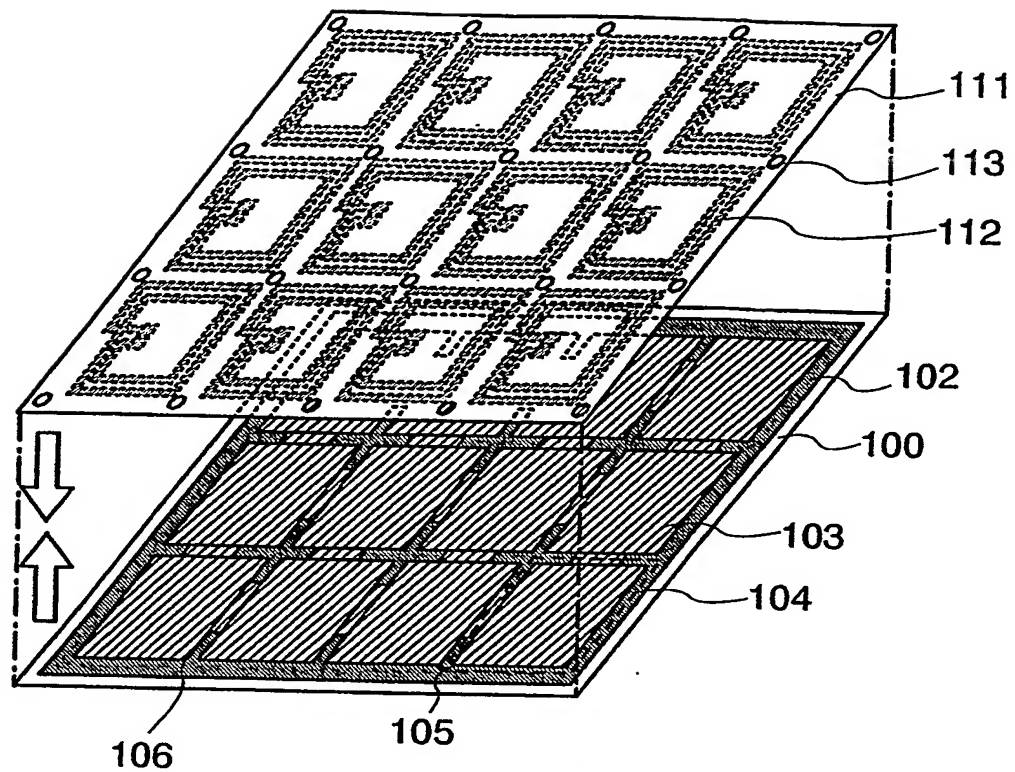


FIG. 20A

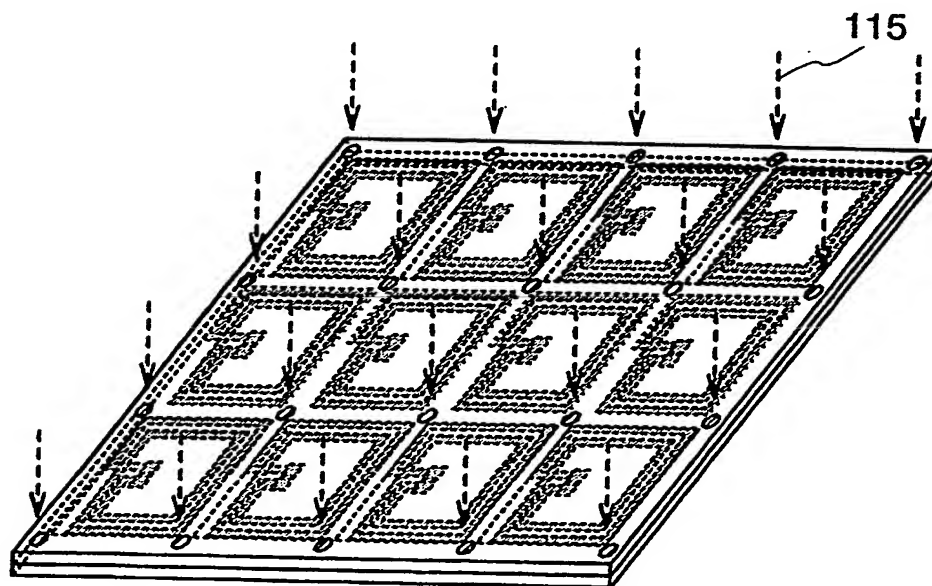


FIG. 20B



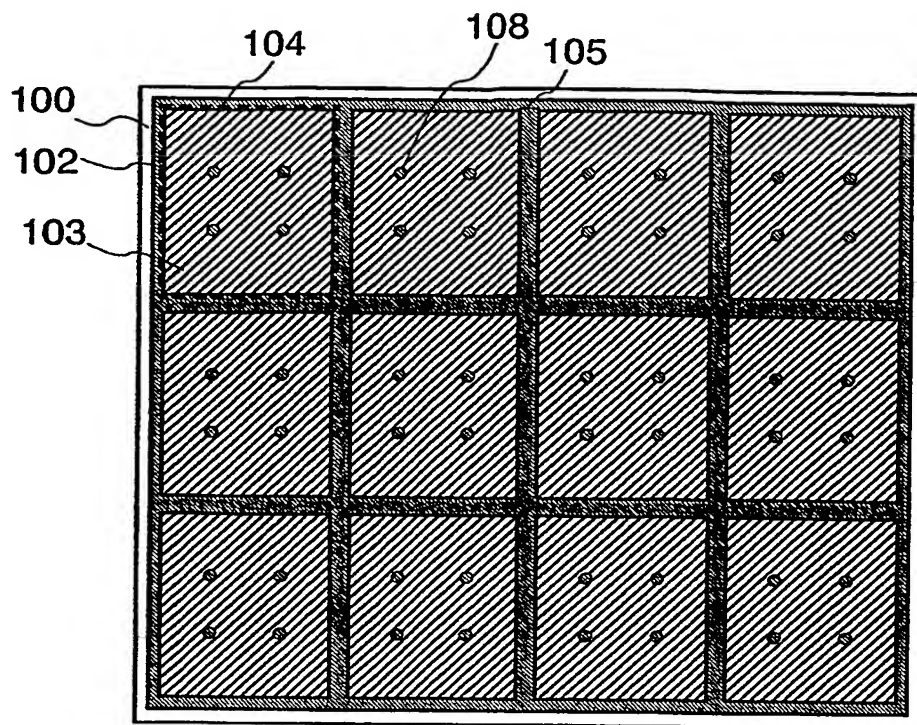


FIG. 21A

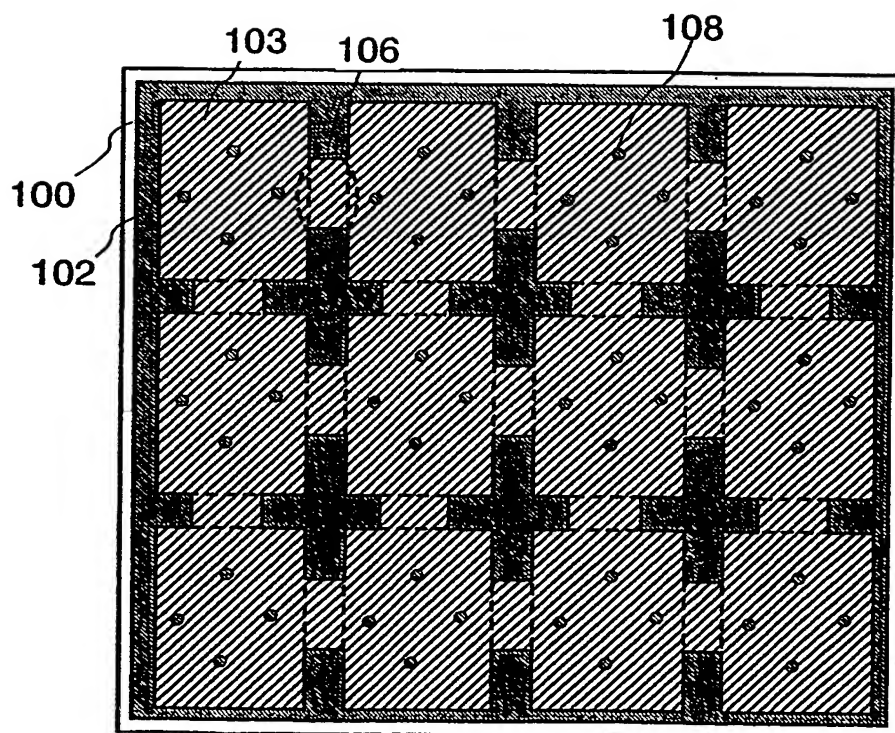


FIG. 21B

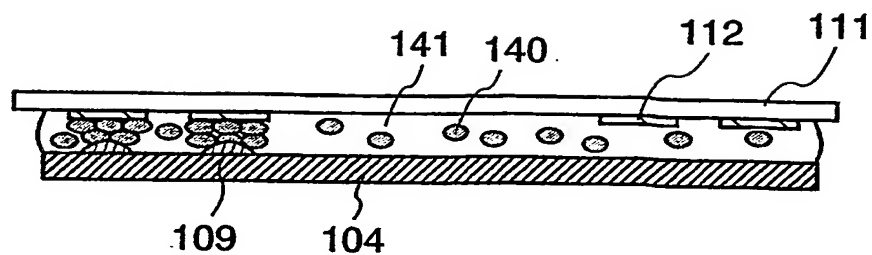


FIG. 22A

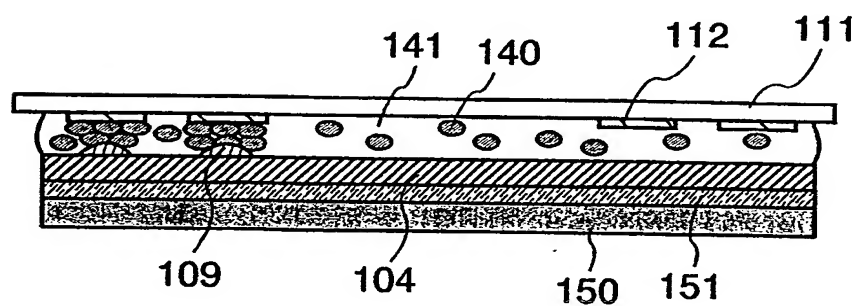


FIG. 22B

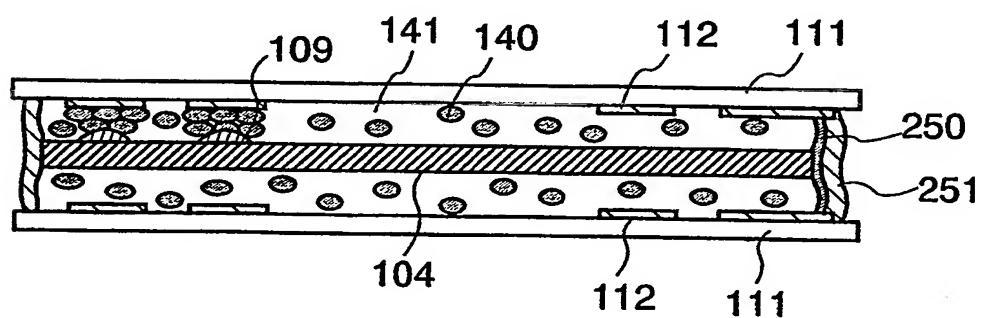


FIG. 22C

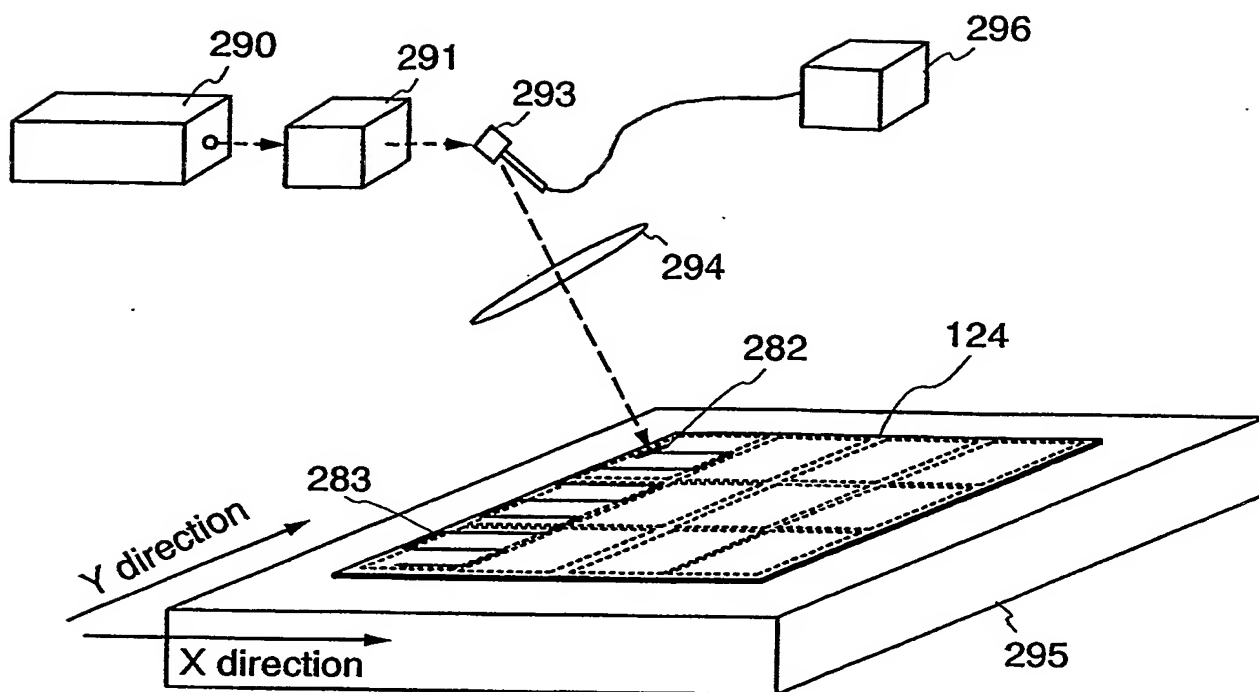


FIG. 23A

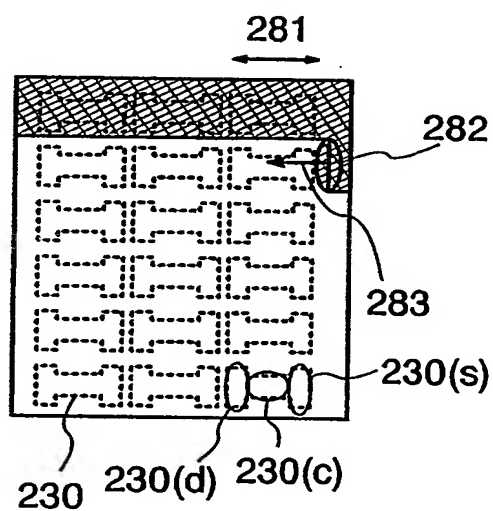


FIG. 23B

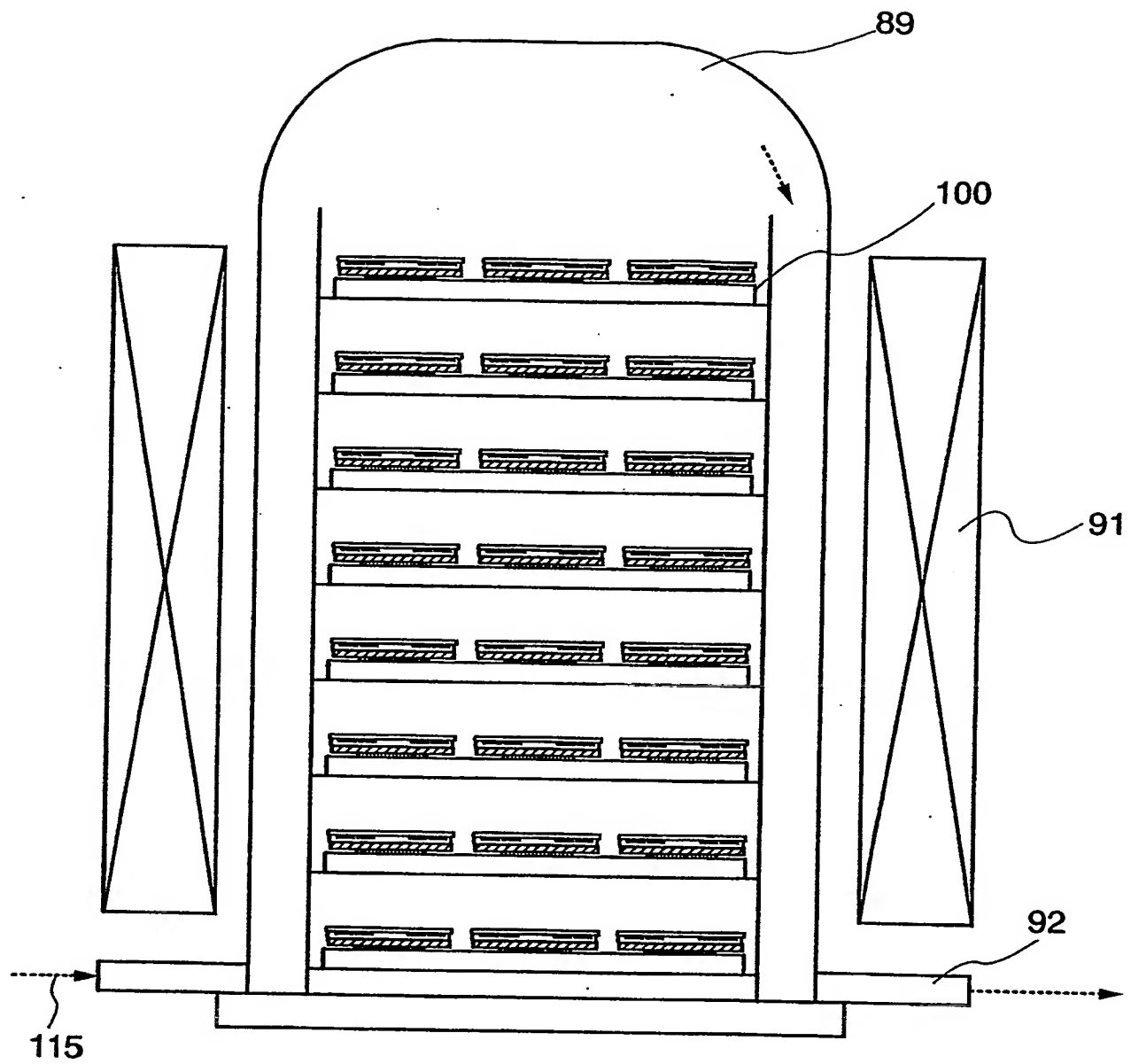


FIG. 24

FIG. 25A

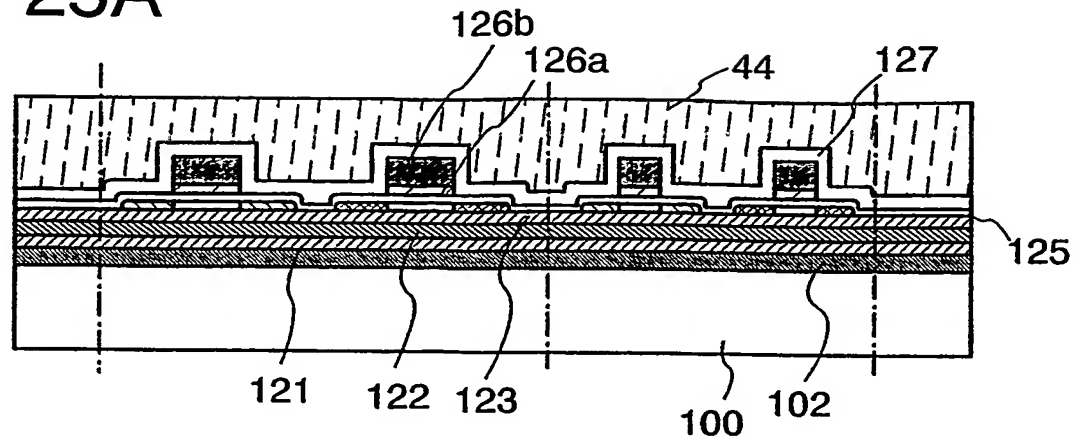


FIG. 25B

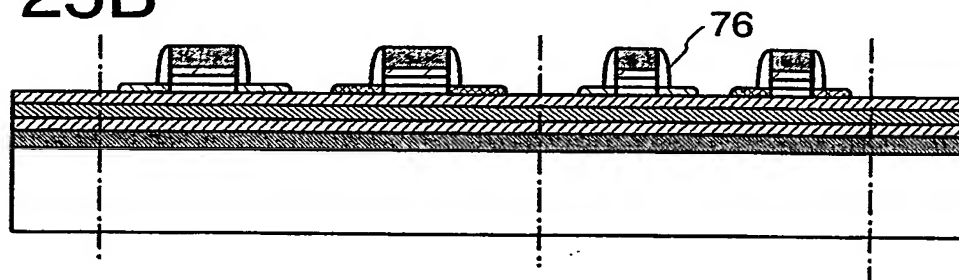


FIG. 25C

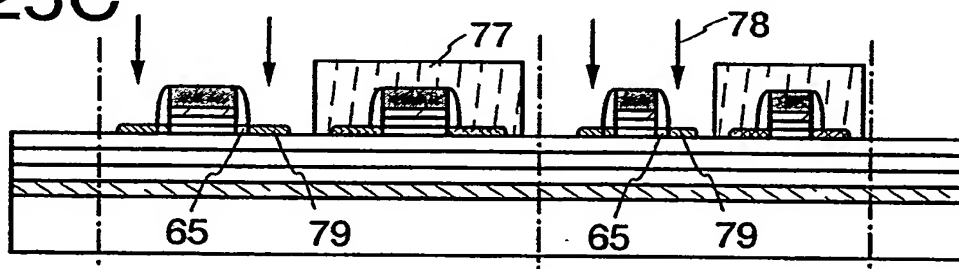


FIG. 25D

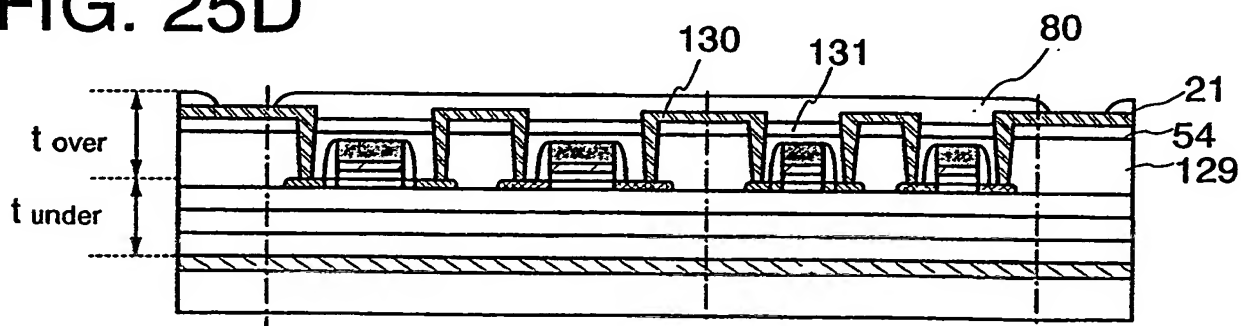


FIG. 26A

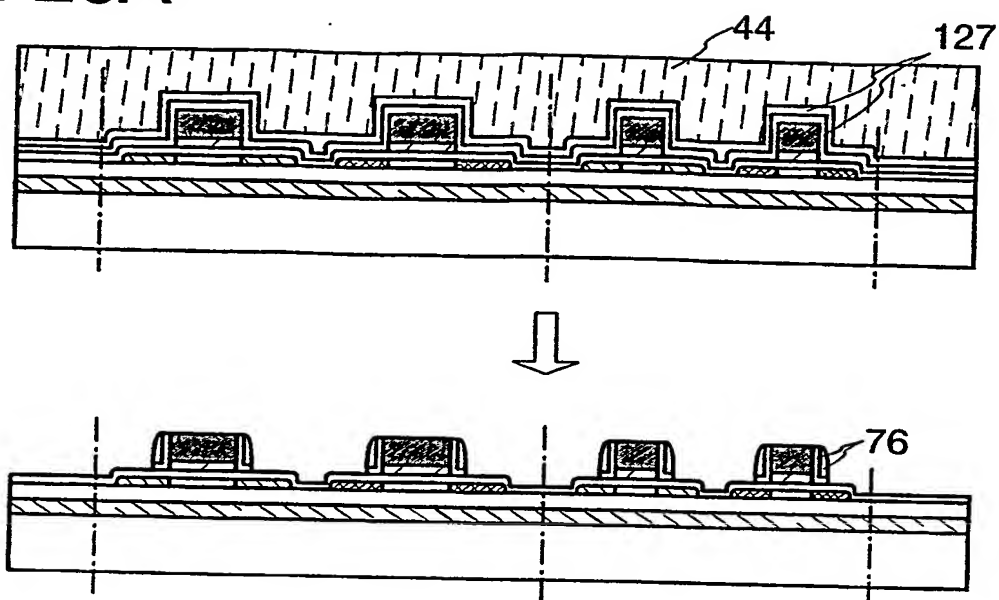
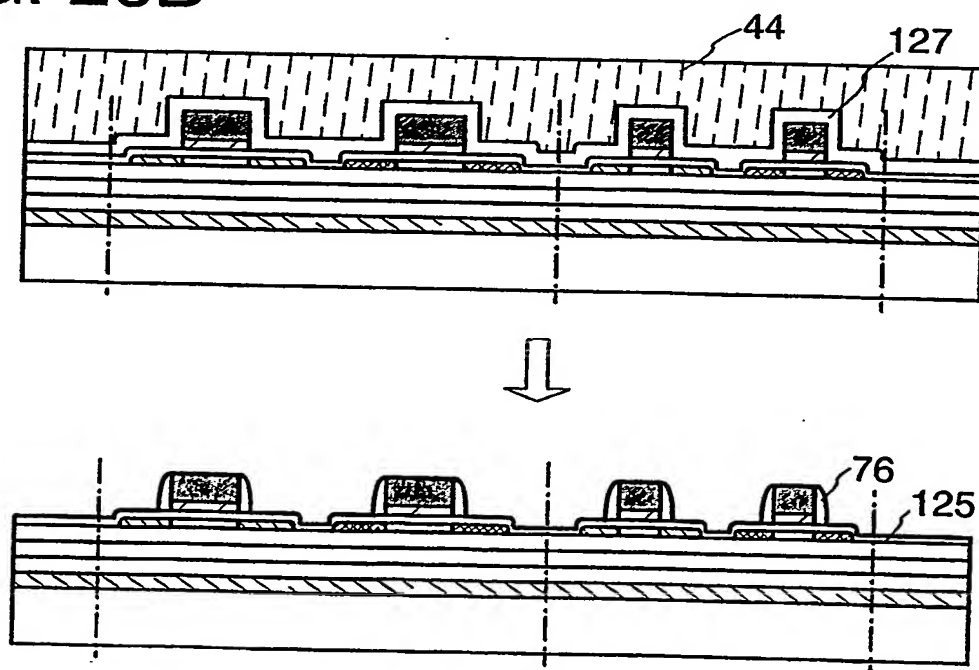


FIG. 26B





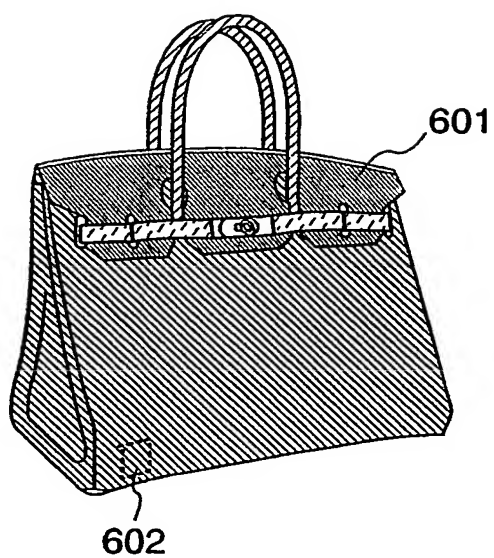


FIG. 27

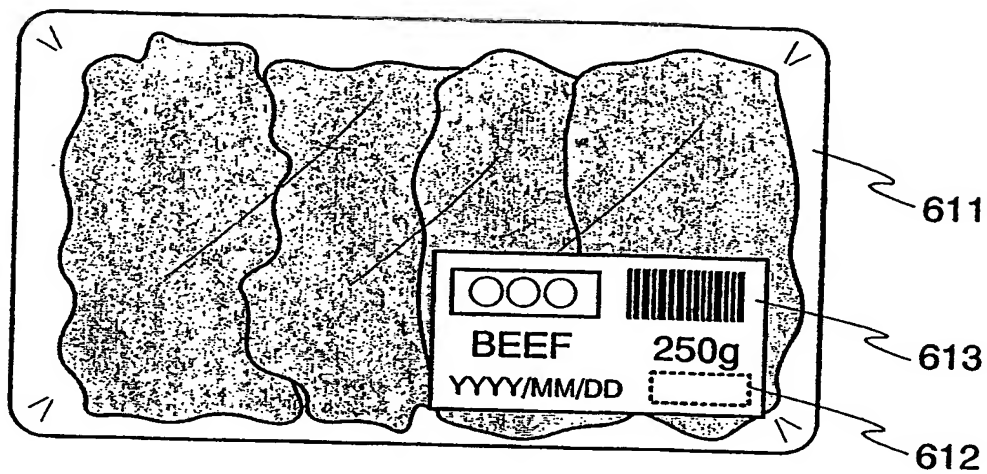


FIG. 28

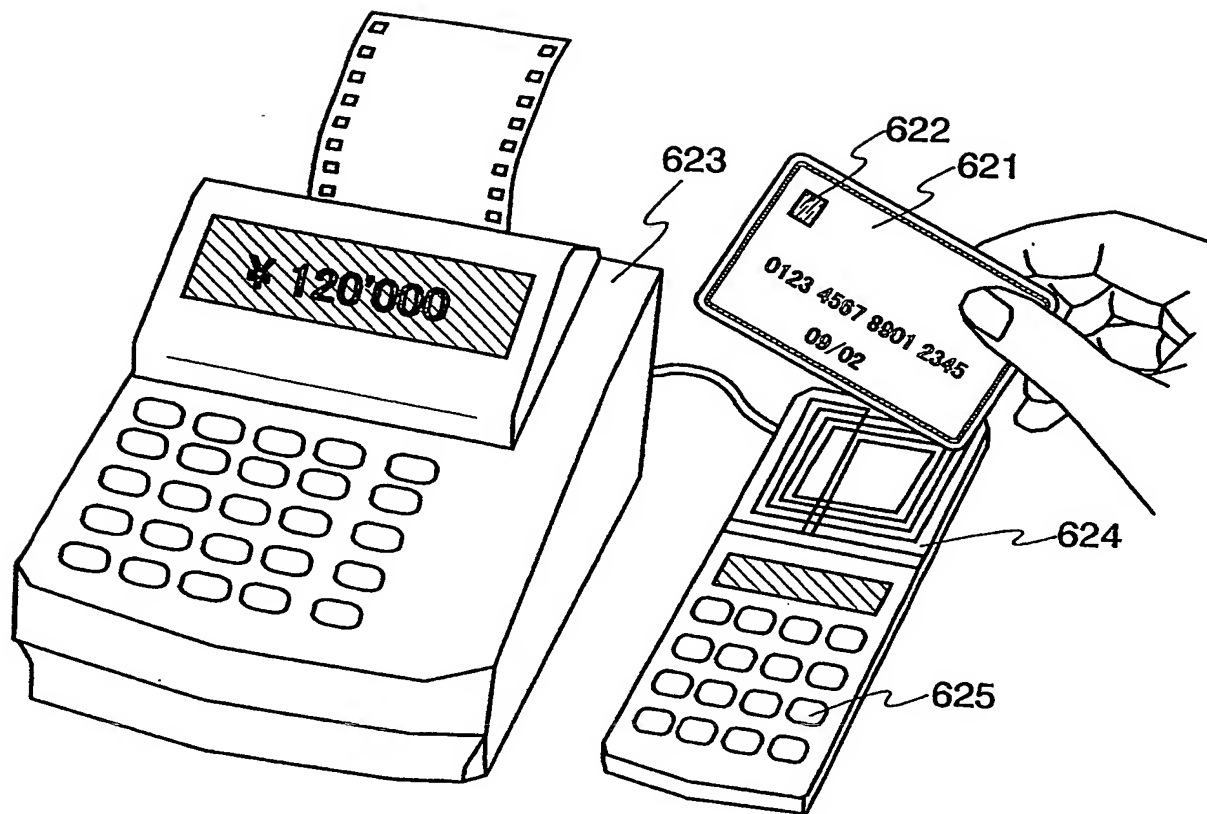


FIG. 29

## EXPLANATION OF REFERENCE

21: Connecting wiring, 44: Resist, 54: Insulating film, 65: Off-set region, 76: Side wall, 77: Resist, 78: Impurity element, 79: High concentration impurity region, 80: Protective film, 89: Bell jar, 91: Heater, 92: Exhaust pipe, 100: Insulating substrate, 102: Separation layer, 103: TFT layer, 104: IDF chip, 105: Groove, 106: Connection region, 108: Opening, 109: Bump, 111: Antenna substrate, 112: Antenna, 113: Opening, 115: Etchant, 121: First insulating film, 122: Second insulating film, 123: Third insulating film, 125: Gate insulating film, 126: Gate electrode, 126a: TaN, 126b: W, 127: First interlayer insulating film, 128n: Thin film transistor, 128p: Thin film transistor, 129: Second interlayer insulating film, 130: Wiring, 131: Fourth insulating film, 135: Connection terminal, 140: Conductor, 141: Anisotropic conductor, 150: Flexible substrate, 151: Adhesive, 160: Nozzle, 180: Label, 181: Beer bottle, 182: Reader/writer, 183: Belt conveyor, 201: Bump, 202: Second substrate, 203: Wiring, 204: Adhesive, 205: Antenna terminal, 230: Semiconductor film, 230(s): Source region, 230(c): Channel formation region, 230(d): Drain region, 250: Conductive film, 251: Insulating film, 280: Arrow direction/Bending direction, 281: Carrier flow direction, 282: Laser spot, 283: Pathway/Laser scanning direction, 290: Laser oscillator, 291: Optical system, 293: Galvanometer mirror, 294:  $f\theta$  lens, 295: XY stage, 296: Control device, 301: Banknote, 302: IDF chip, 311: Check, 312: IDF chip, 321: Stock certificate, 322: IDF chip, 331: Book, 332: IDF chip, 341: DVD, 342: IDF chip, 401: Medicine bottle, 402: IDF chip, 403: Label, 410: Reader/writer, 420: Personal computer, 421: Display portion, 430: Cellular phone, 431: Antenna, 432: Display portion, 501: Antenna coil, 502: Capacitor element, 503: Demodulation circuit, 504: Modulation circuit, 505: Rectifier circuit, 506: Microprocessor, 507: Memory, 508: Switch, 511: Antenna coil, 512: Modulation circuit, 513: Oscillating means, 514: Detection demodulation circuit, 515: Gate ASIC, 516: Microprocessor, 517: Memory, 518: power source, 519: Signal interface, 601: Bag, 602: IDF chip, 611: Package, 612: IDF chip, 613: Label, 621: Card, 622: IDF chip, 623: Cash register, 624: Reader/writer, and 625: Key pad.

**This Page is Inserted by IFW Indexing and Scanning  
Operations and is not part of the Official Record**

**BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- ☒ BLACK BORDERS
- ☐ IMAGE CUT OFF AT TOP, BOTTOM OR SIDES
- ☐ FADED TEXT OR DRAWING
- ☐ BLURRED OR ILLEGIBLE TEXT OR DRAWING
- ☐ SKEWED/SLANTED IMAGES
- ☒ COLOR OR BLACK AND WHITE PHOTOGRAPHS
- ☐ GRAY SCALE DOCUMENTS
- ☐ LINES OR MARKS ON ORIGINAL DOCUMENT
- ☐ REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY
- ☐ OTHER: \_\_\_\_\_

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.**